

Using Large-Signal Measurements for Transistor Characterization and Model Verification in a Device Modeling Program

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Dominique Schreurs¹, and Bart Nauwelaers¹

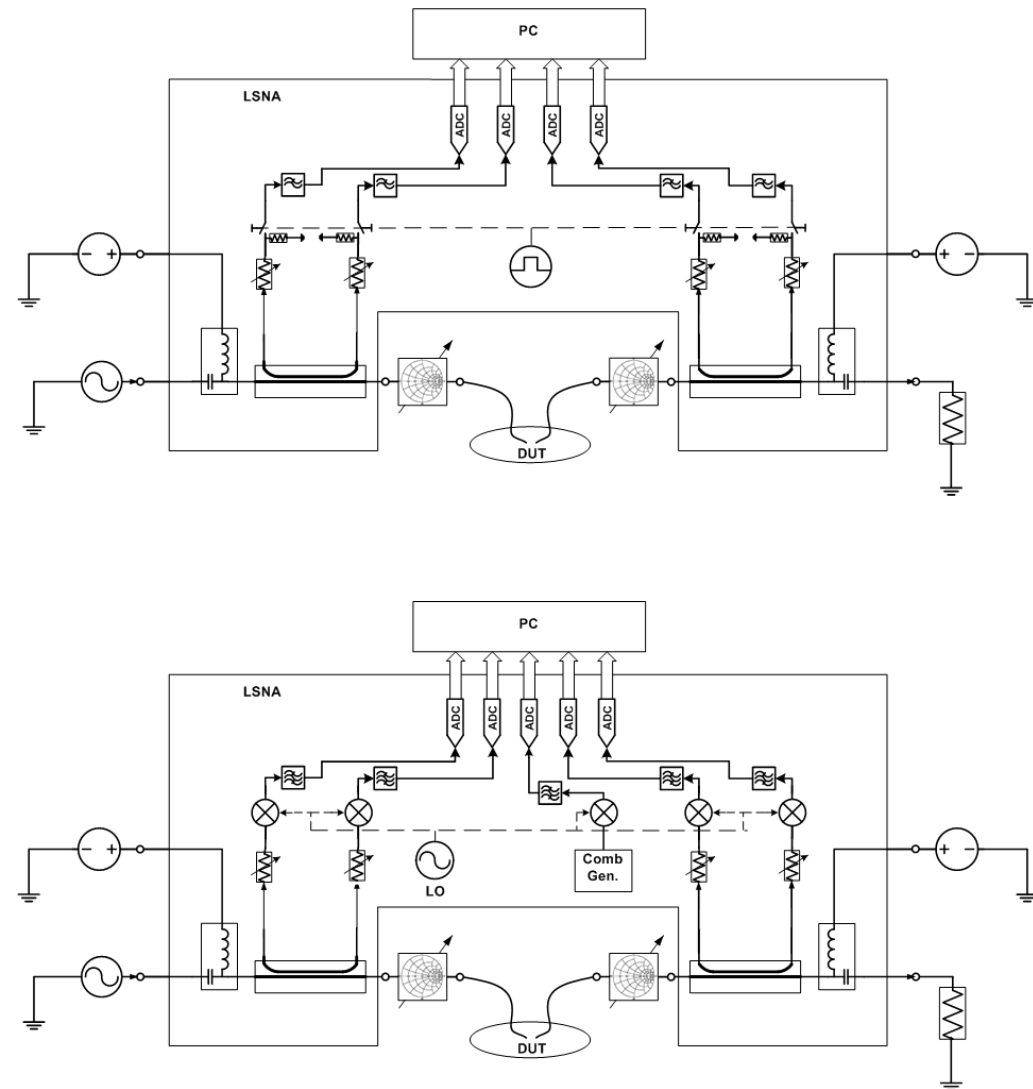
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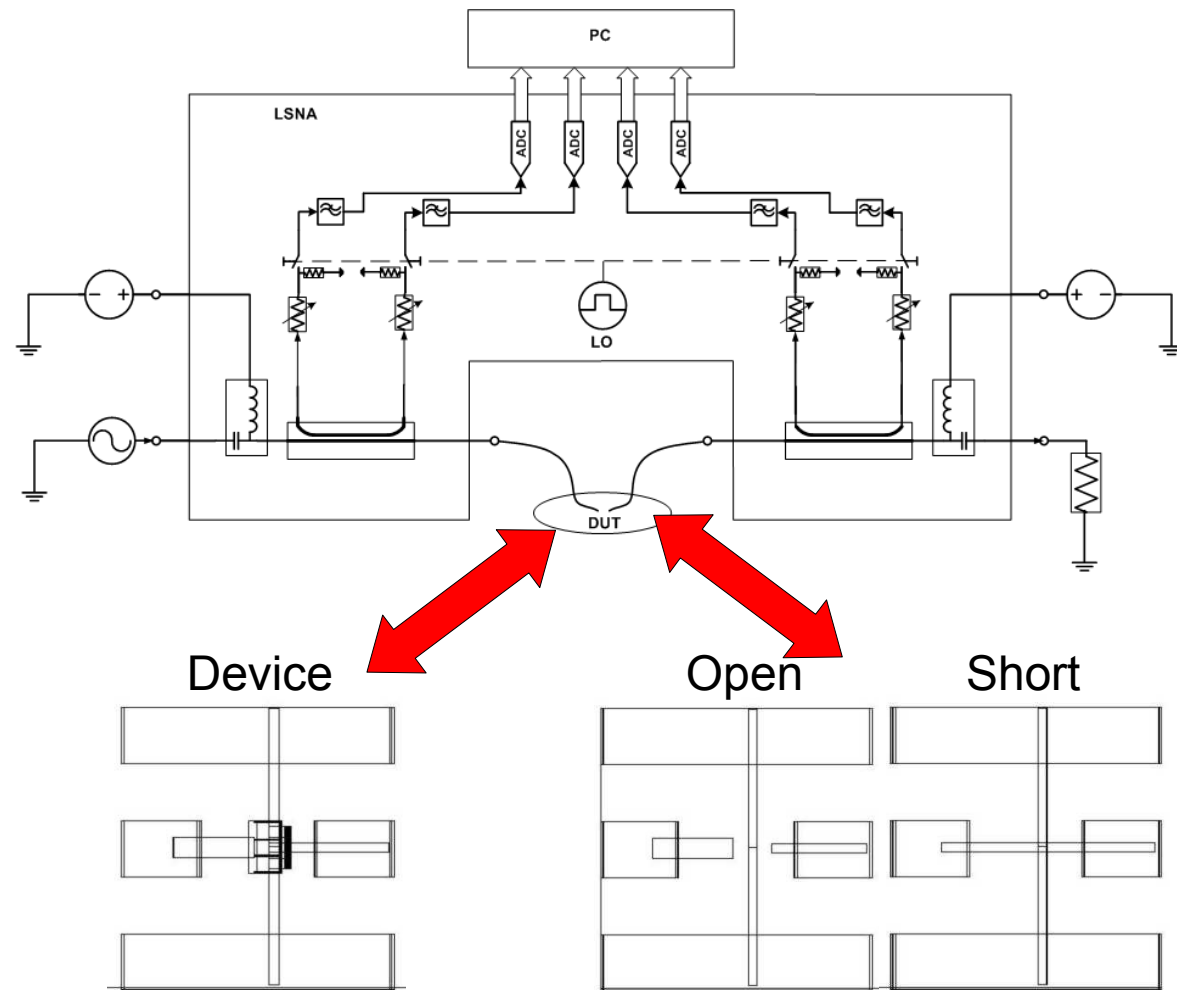
³ NMDG N.V., Belgium.

- Introduction
- Large-signal measurement data in a device modeling program
 - Example: IC-CAP
- Transistor characterization
 - Example: MOSFET
- Model verification
 - Example: Angelov model
- Results
- Conclusions

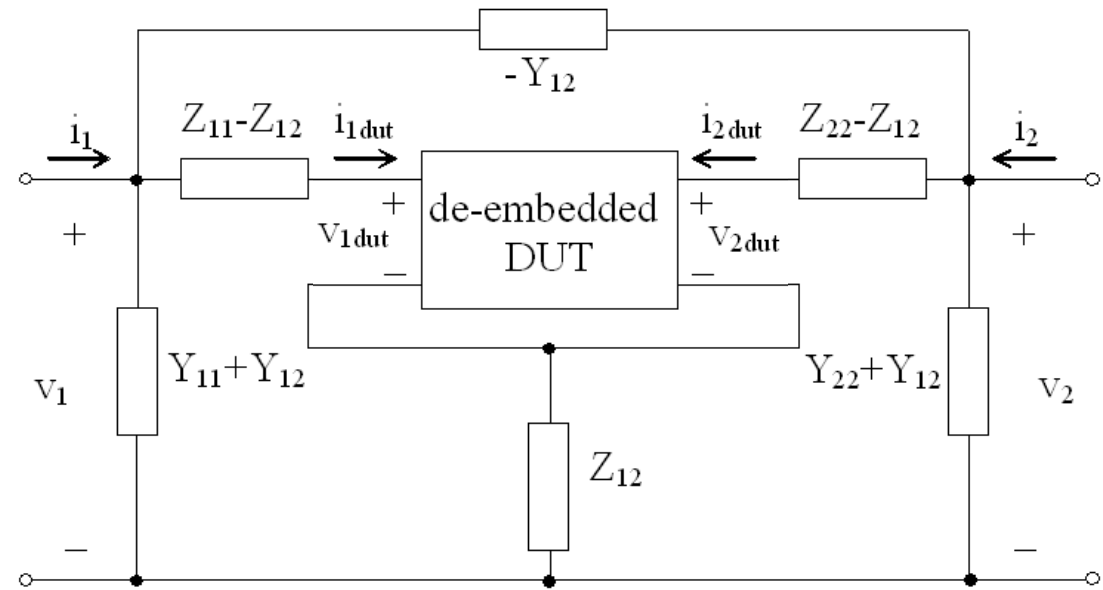
- Large-signal network analyzer (LSNA)
 - Amplitude and phase of all harmonics and intermods up to 50 GHz
 - Realistic signals:
 - 1-tone, 2-tone, N-tone up to +40 dBm
 - DC, small-signal, large-signal behavior
 - Non-50 Ω environment
 - Sampler/Mixer-based



- Large-signal on-wafer measurements
 - Device:
 - Frequency sweep
 - RF power sweep
 - DC bias sweep
 - De-embedding structures:
 - Frequency sweep



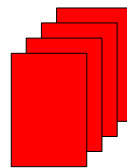
- Large-signal on-wafer measurements
- Data processing
 - De-embedding
 - Transformation to the program specific format



$Y_{ij} \rightarrow$ Y-parameters of open

$Z_{ij} \rightarrow$ Z-parameters of short, after de-embedding of open effects.

MDM files

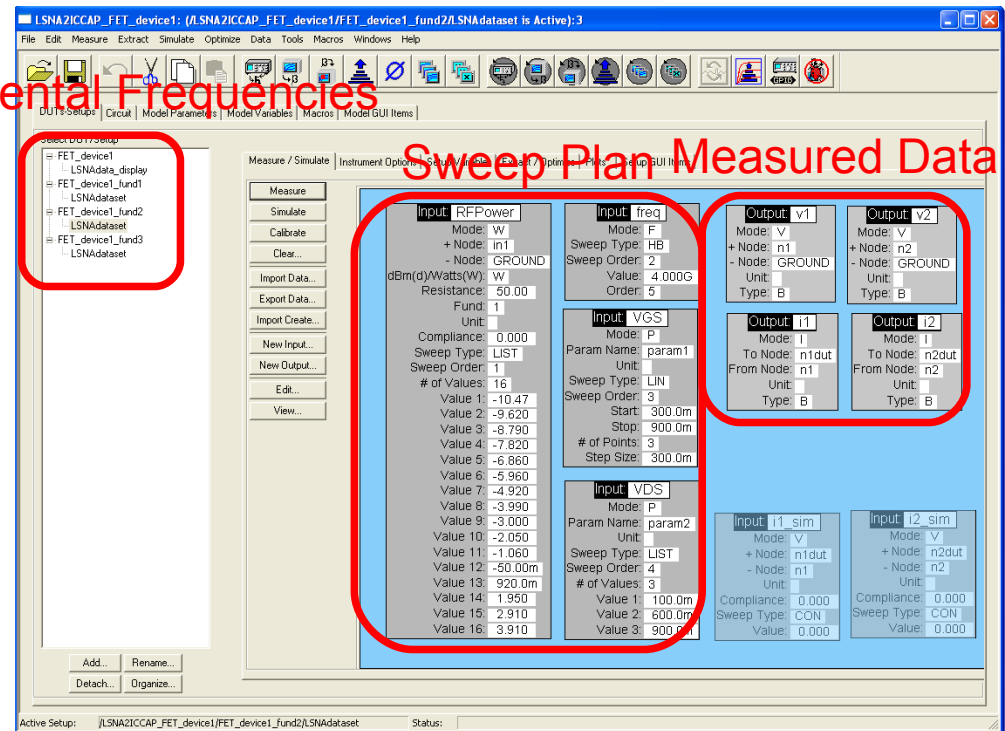


$$\begin{aligned} i_{1dut} &= i_1 - v_1(Y_{11} + Y_{12}) - (v_2 - v_1)Y_{12} = i_1 - v_1Y_{11} - v_2Y_{12} \\ i_{2dut} &= i_2 - v_2(Y_{22} + Y_{12}) - (v_1 - v_2)Y_{12} = i_2 - v_2Y_{22} - v_1Y_{12} \\ v_{1dut} &= v_1 - i_{1dut}Z_{11} - i_{2dut}Z_{12} \\ v_{2dut} &= v_2 - i_{2dut}Z_{22} - i_{1dut}Z_{12} \end{aligned}$$

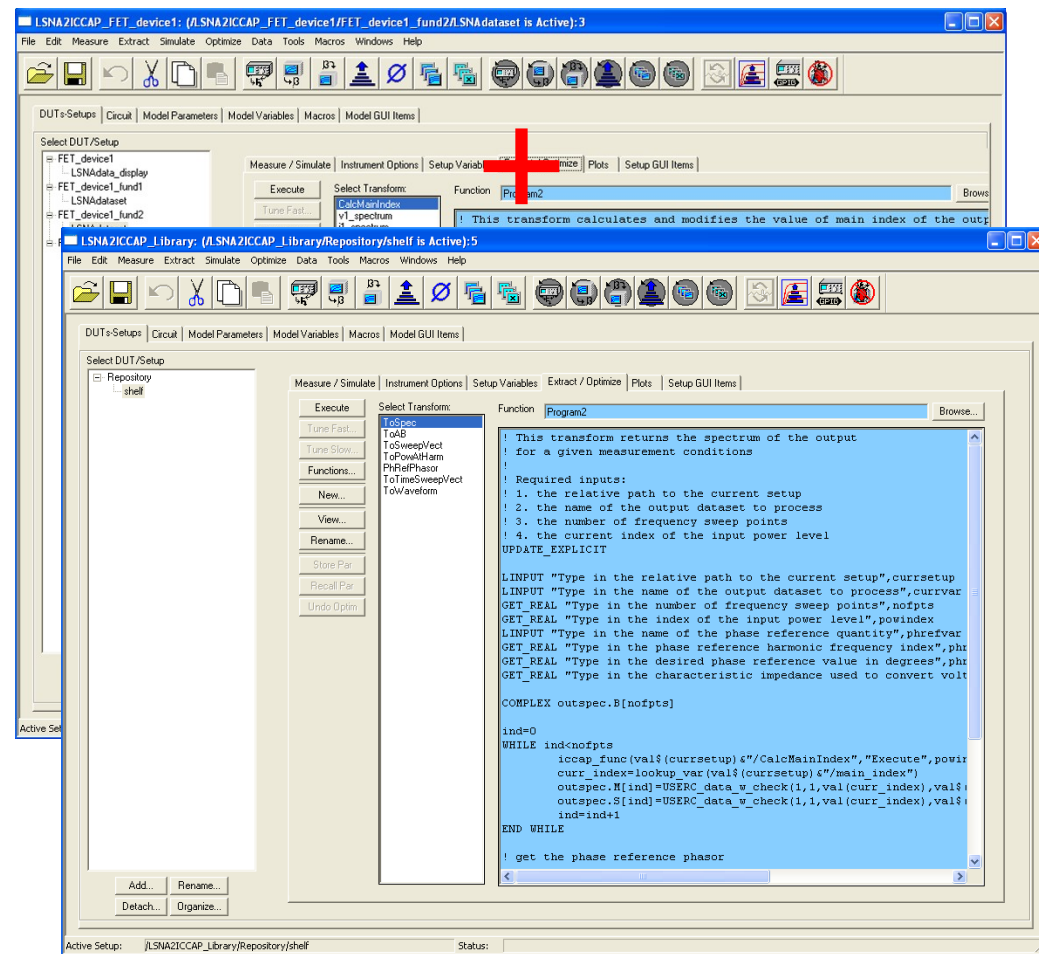
- Large-signal on-wafer measurements
- Data processing
- Implementation in the device modeling program
 - Measured data

Fundamental Frequencies

Sweep Plan Measured Data



- Large-signal on-wafer measurements
- Data processing
- Implementation in the device modeling program
 - Measured data
 - Data processing routines

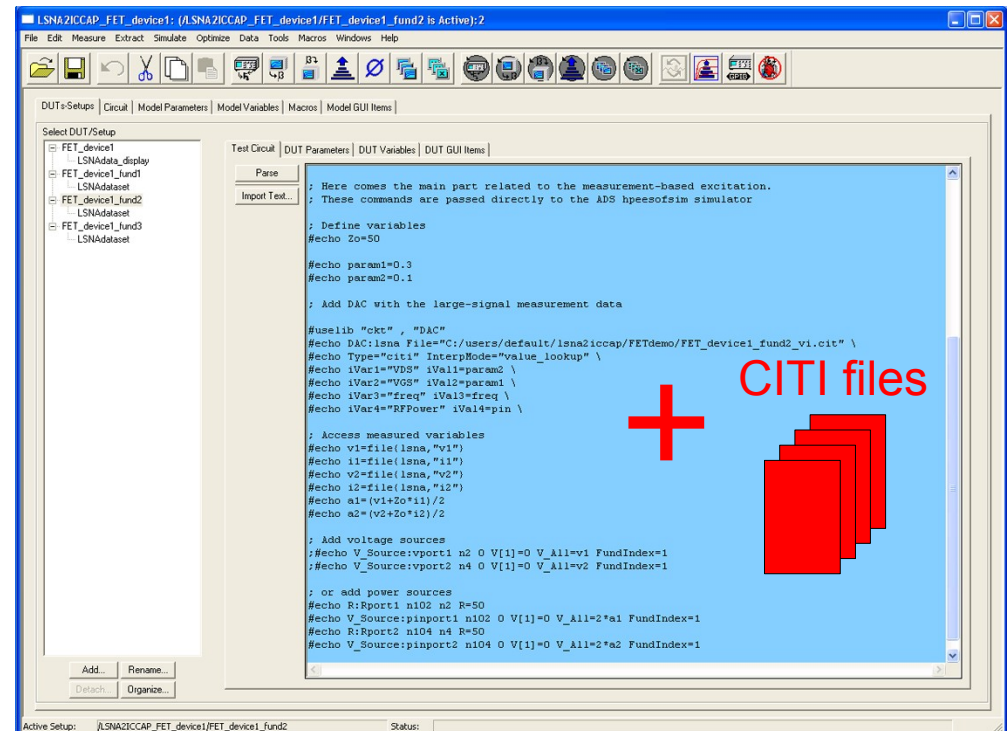


- Large-signal on-wafer measurements

- Data processing

- Implementation in the device modeling program

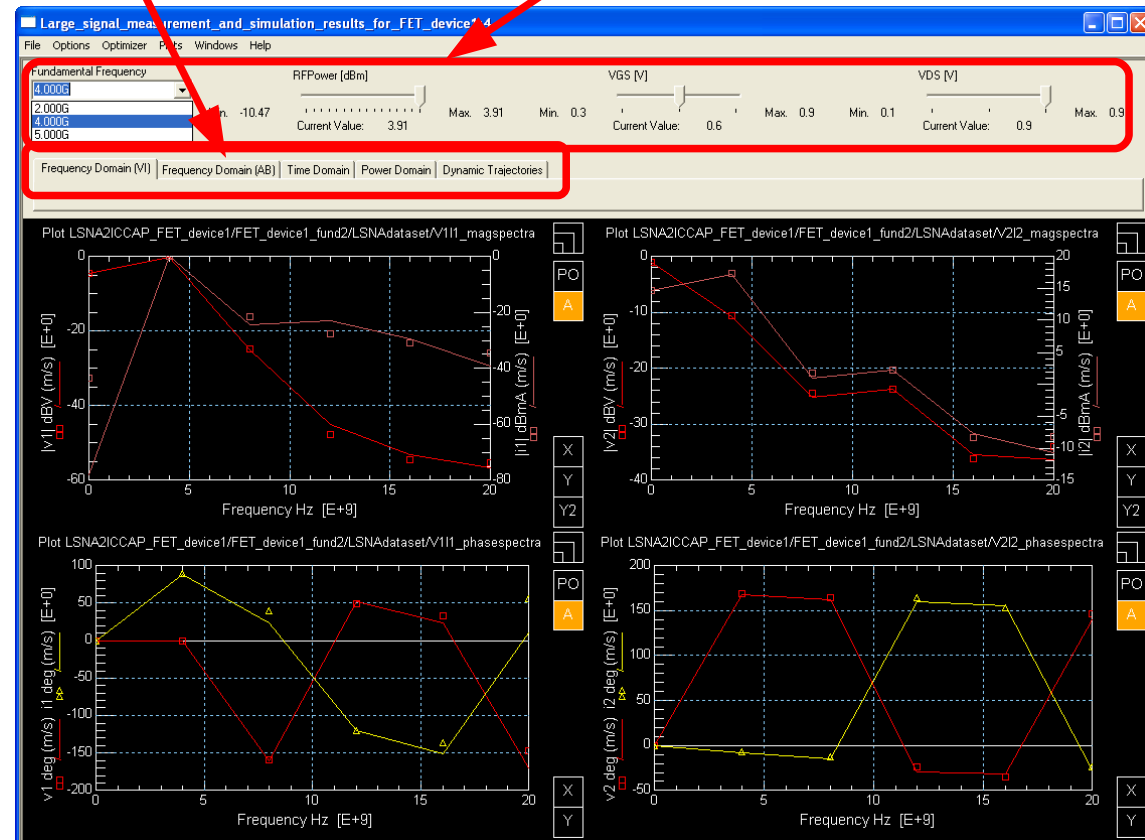
- Measured data
- Data processing routines
- Link to simulator



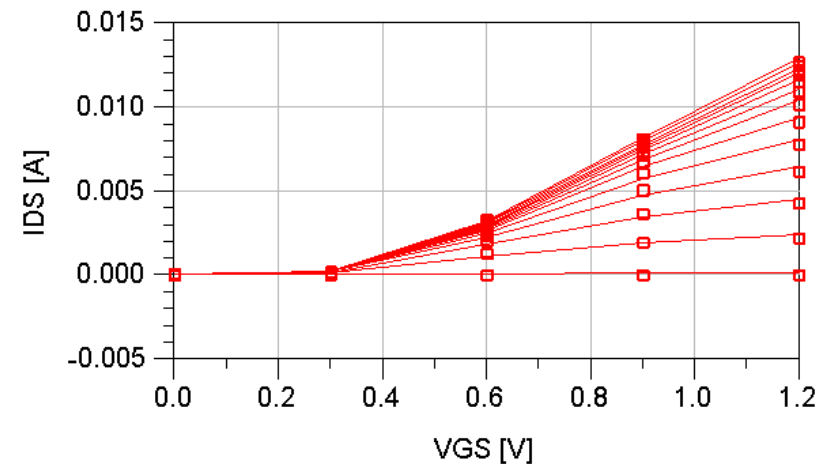
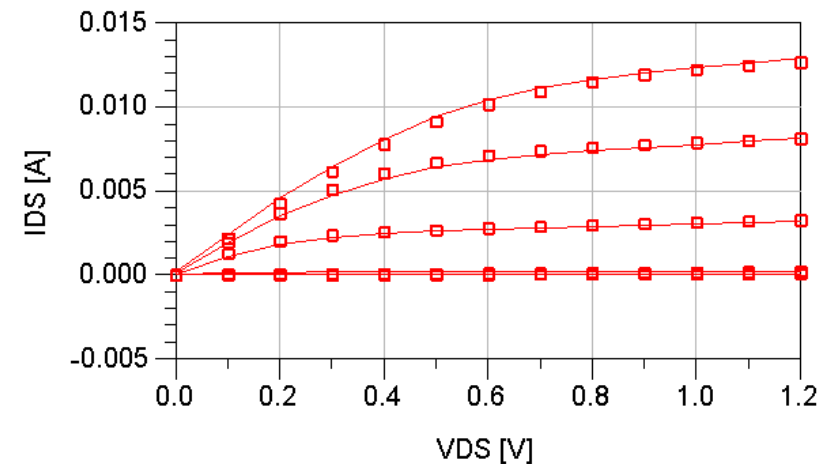
- Large-signal on-wafer measurements
- Data processing
- Implementation in the device modeling program
 - Measured data
 - Data processing routines
 - Link to simulator
 - Graphic user interface

Selecting display domain

Selecting measurement conditions

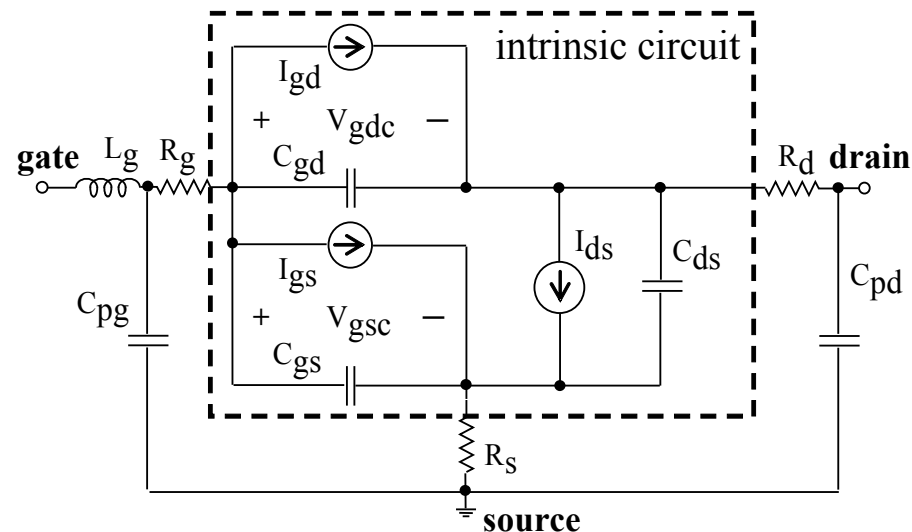


- On-wafer DUT:
 - MOSFET
 - Open & Short de-embedding structures
- LSNA measurements:
 - f_0 : 2, 4, 5 GHz
 - P_{in} : -10 $\rightarrow$ +4 dBm
 - V_{GS} : 0.3, 0.6, 0.9 V
 - V_{DS} : 0.1, 0.6, 0.9 V



• Angelov MOSFET model:

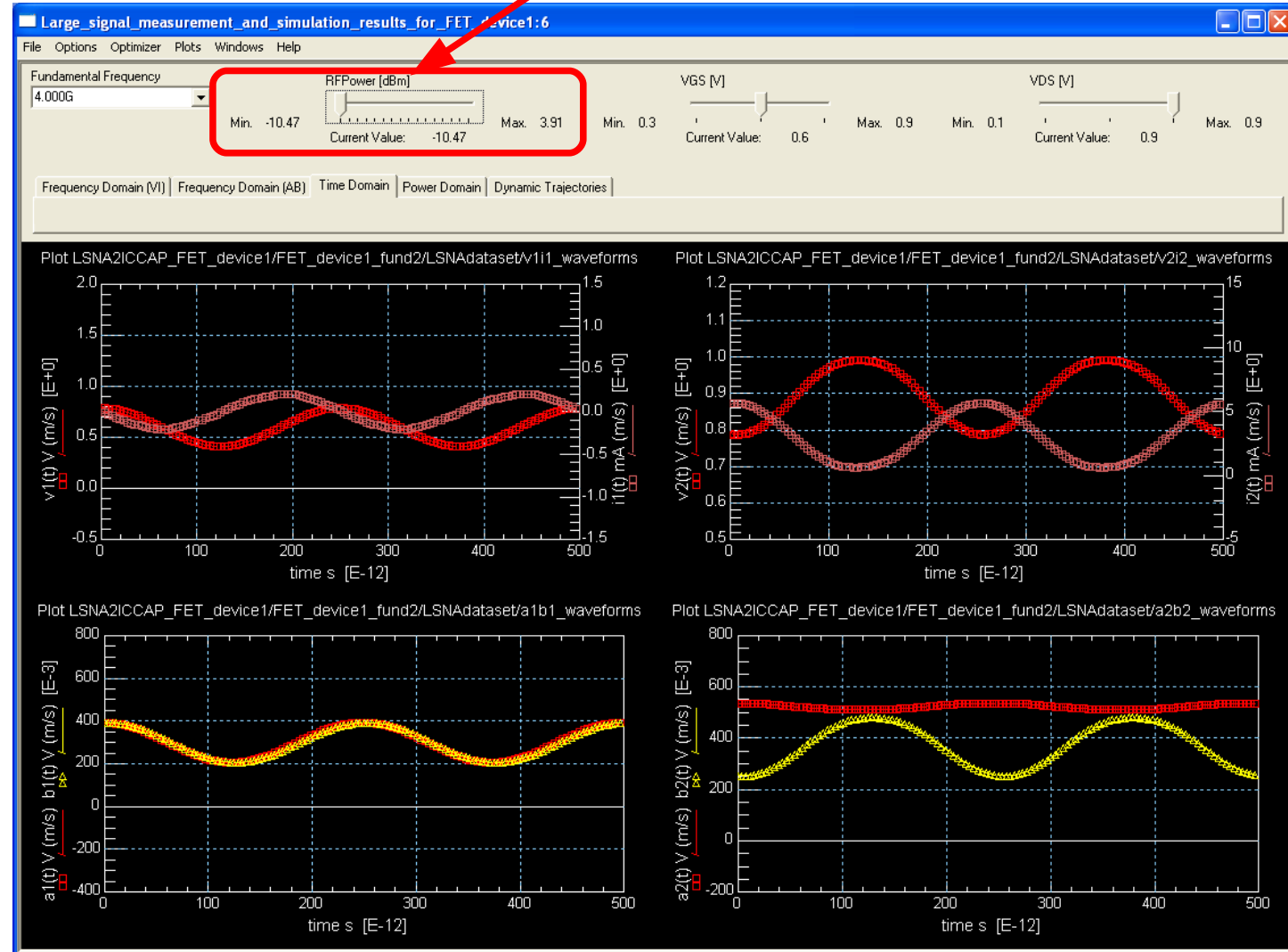
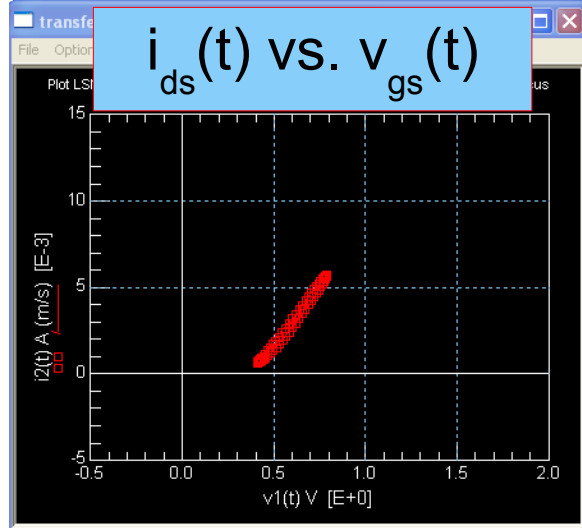
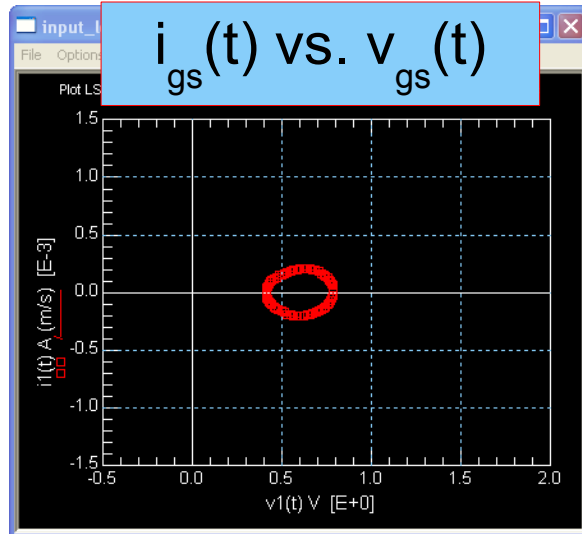
- Neglected self-heating and intrinsic non quasi static effects,
- Capacitance mode,
- Extracted from DC and S-parameter measurements
- Tuned around:
 $V_{GS} = 0.6 \text{ V}$, $V_{DS} = 0.9 \text{ V}$,
 $f_0 = 4 \text{ GHz}$



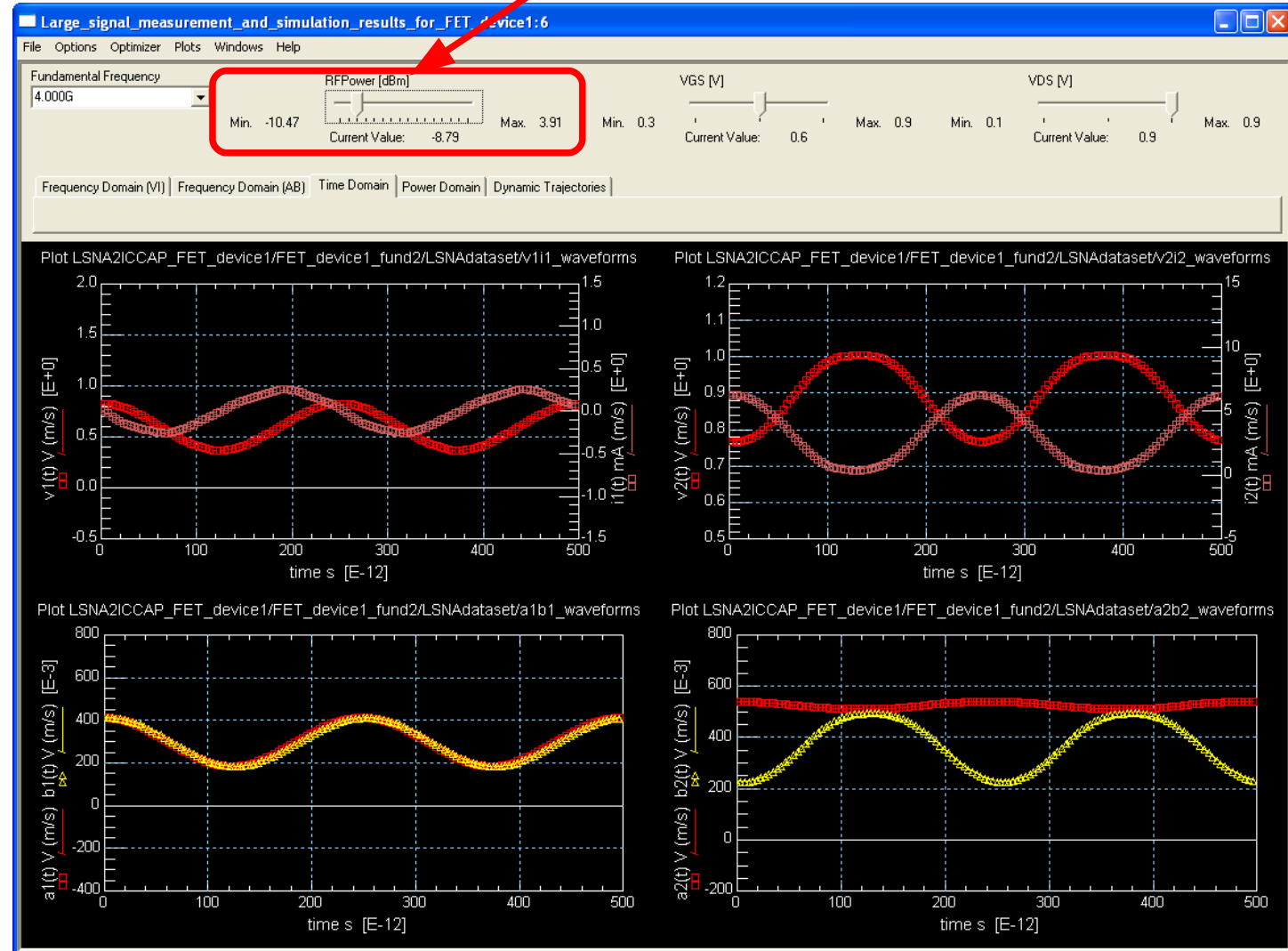
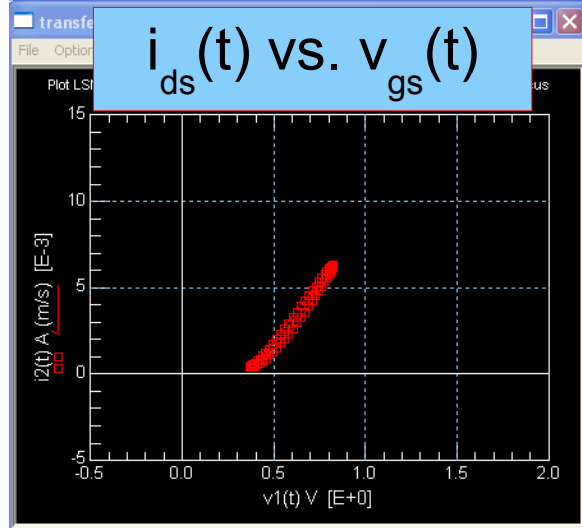
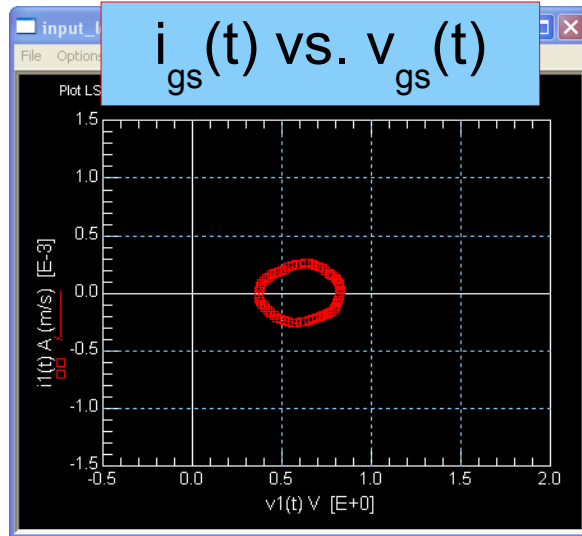
```

model AngelovM1 Angelov B1=0 P31=0.54852 Rcmn=0kOhm
Idsmo=1 B2=3.92 P40=1.2 Rc=0kOhm
Igm=1 Lsb0=0 P41=1.71519 Crf=35.3284fF
Capmo=1 Vtr=4 P111=0.001 Rcin=0kOhm
Ipk0=0.0066 Vsb2=0 Ij=0.0025 Crfin=0fF
Vpks=0.84 Cds=28.331fF Pg=0.0002 Rth=50
Dvpks=0.027 Cgs0=5fF Vjg=0.9 Cth=0
P1=2.5 Cgs0=5fF Rg=22.4 Tcipk0=0
P2=0.1 Cgdpi=4.5446fF Rd=10.7 Tcp1=0
P3=6.2 Cgd0=5.06055fF Rs=11.2 Tccgs0=0
Alphar=2.5 Cgdpe=0fF Ri=0 Tccgd0=0
Alphas=0.5 P10=1 Rgd=0 Tcls0=0
Vkn=0.5 P11=1.71519 Lg=0pH Tcr=0
Lambda=0.1 P20=0.2 Ld=0 Tccrf=0
Lambda1=0.07 P21=0.54852 Ls=0 Tnom=25
Lv=0 P30=0.25 Tau=0ps
    
```

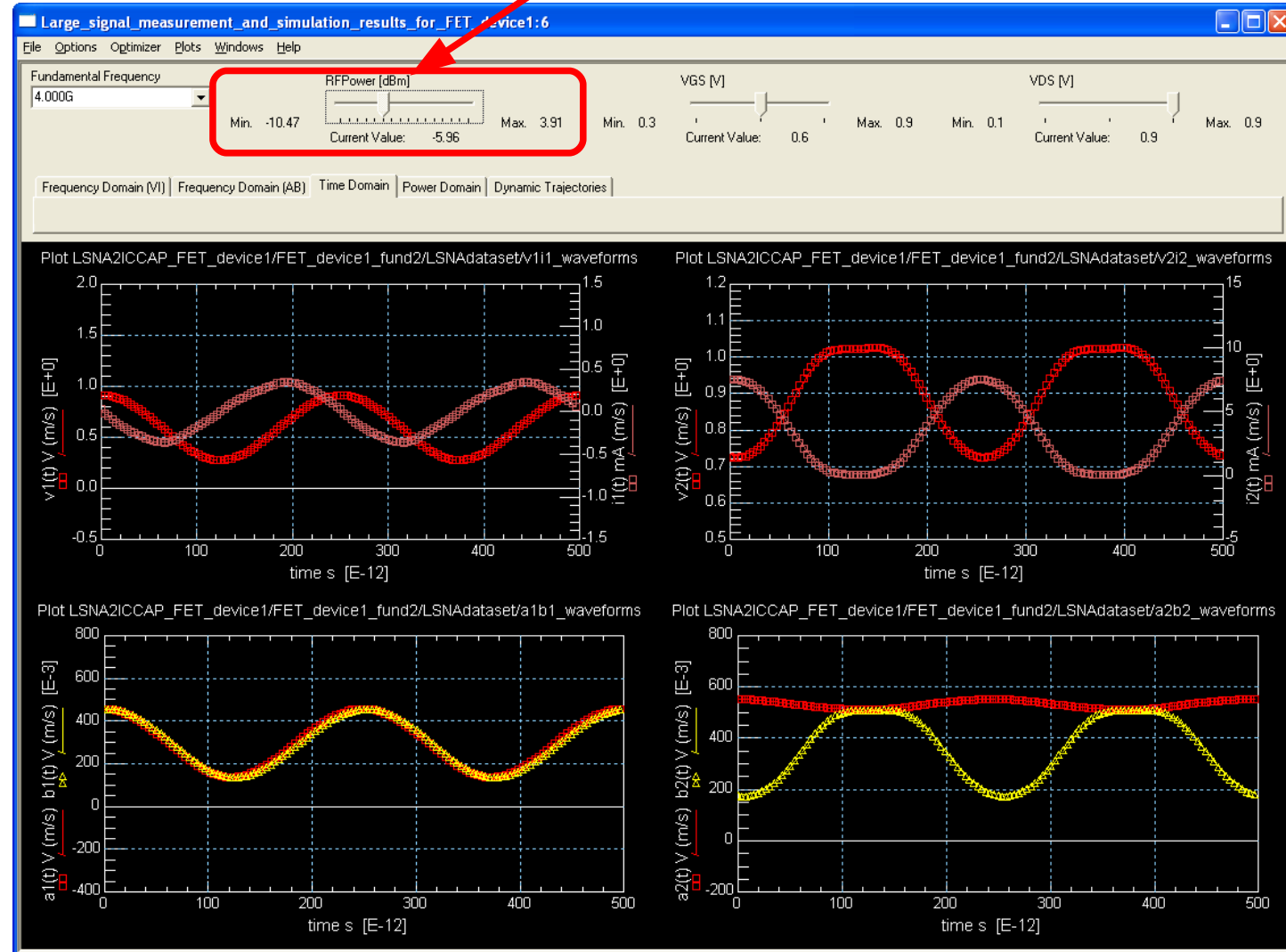
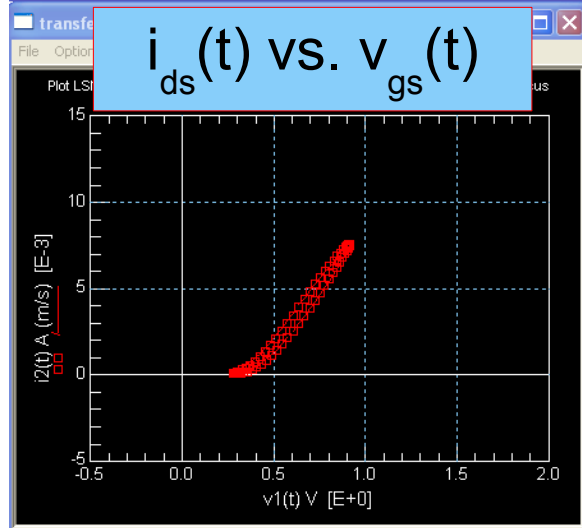
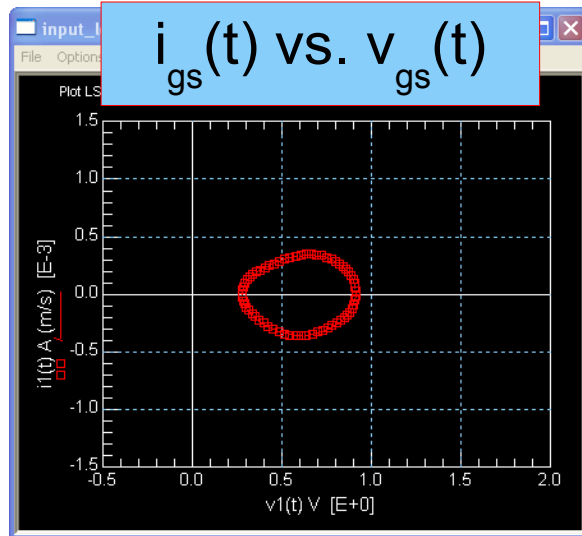
$f_0 = 4 \text{ GHz}$, $V_{GS} = 0.6 \text{ V}$, $V_{DS} = 0.9 \text{ V}$, **RF power: -10.47 $\rightarrow$ +3.91 dBm**



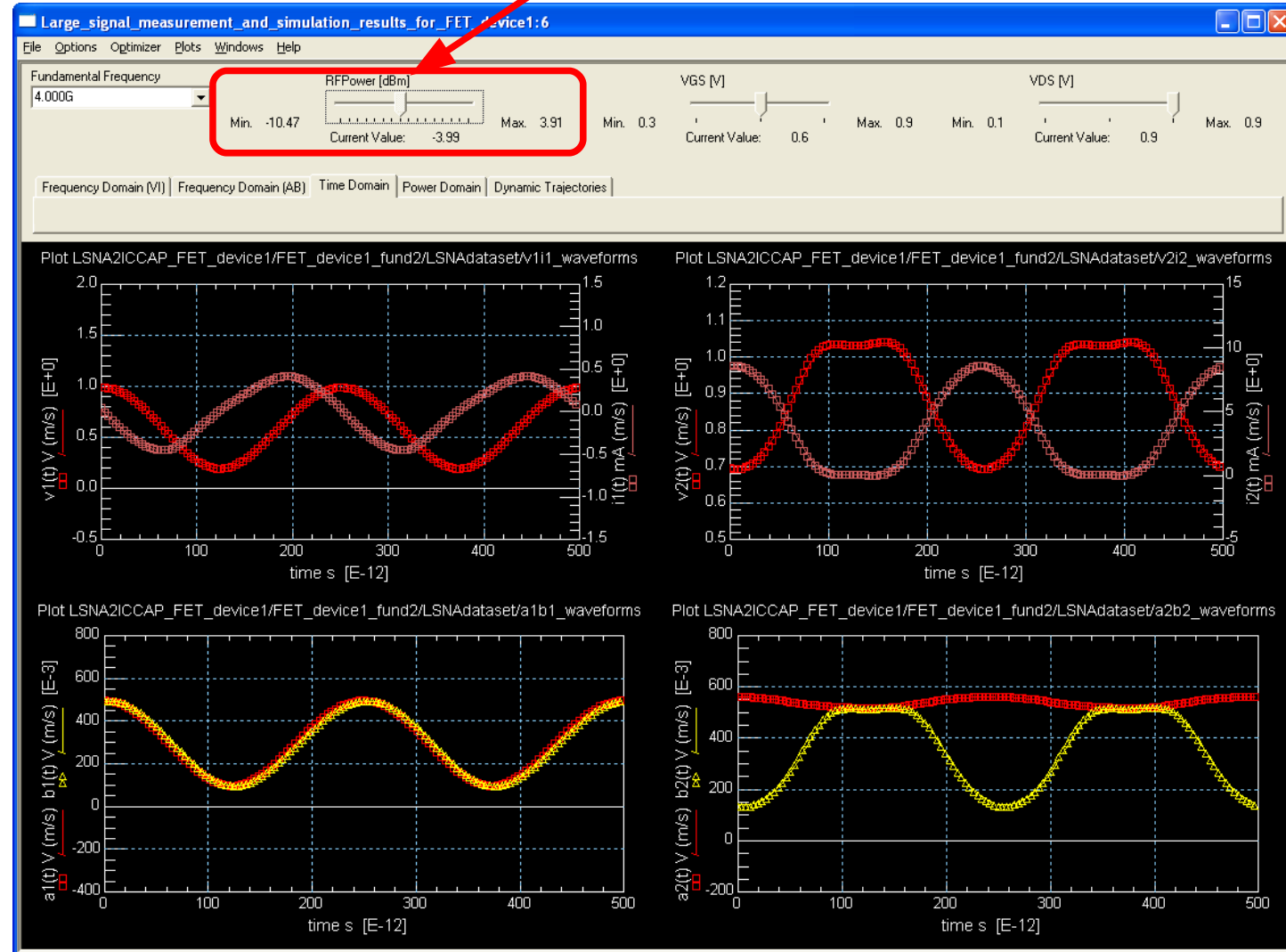
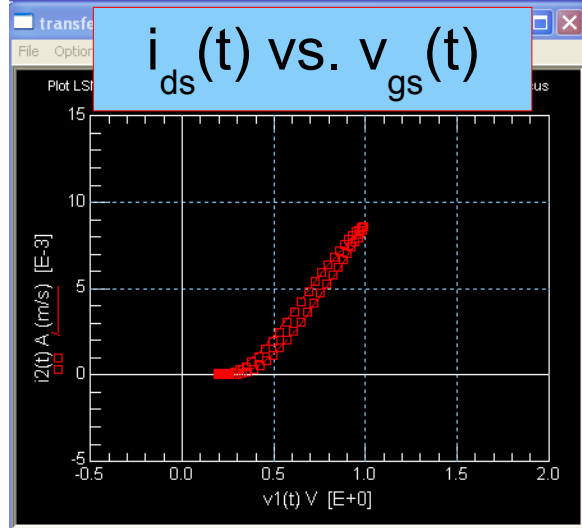
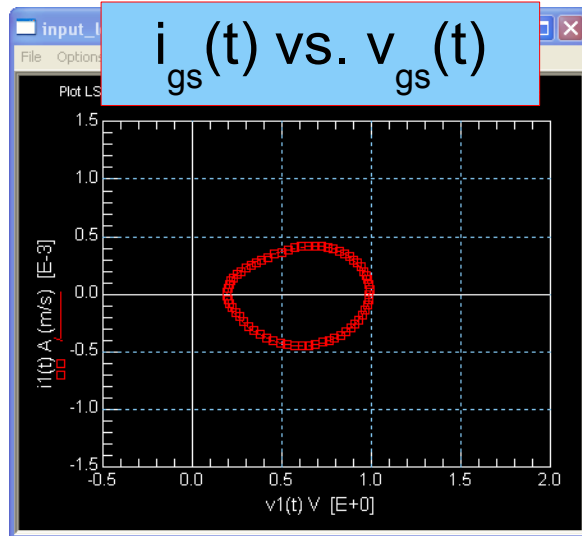
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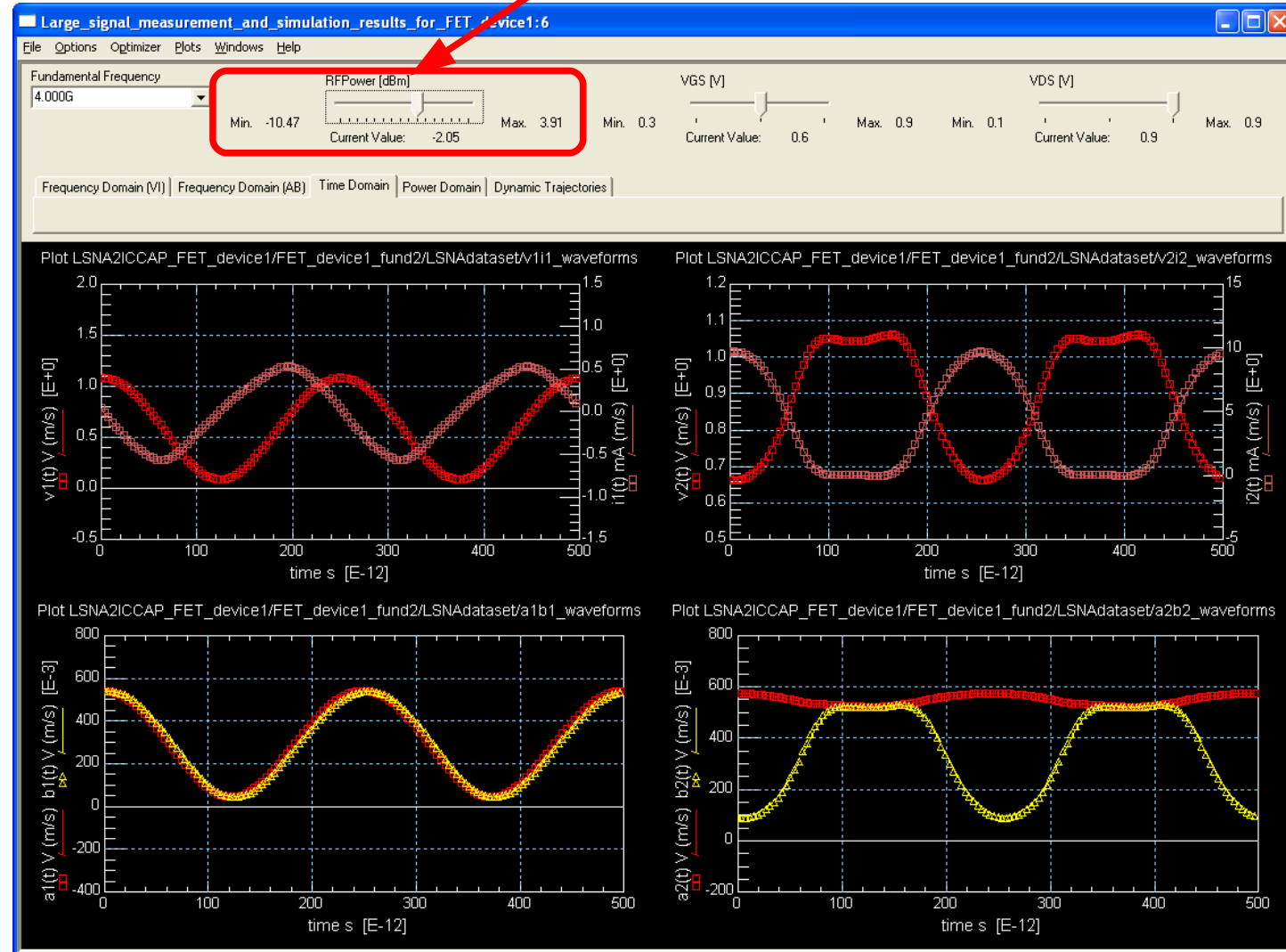
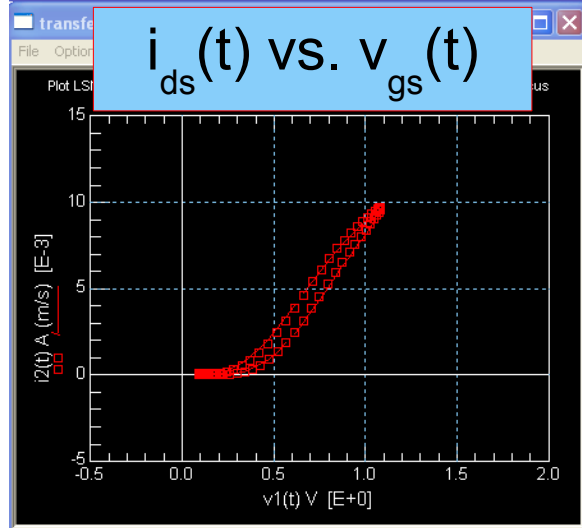
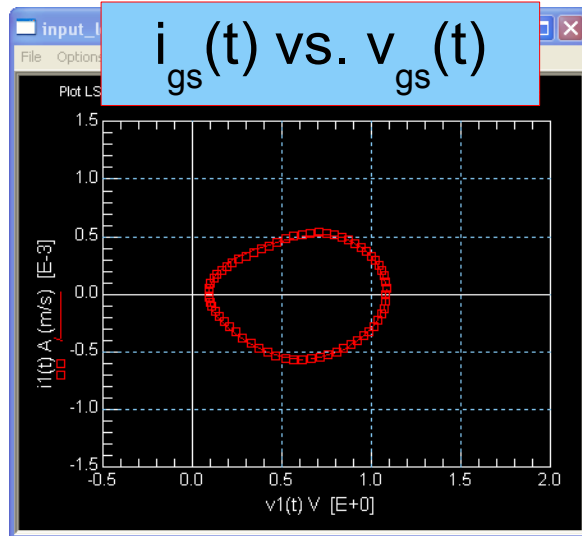
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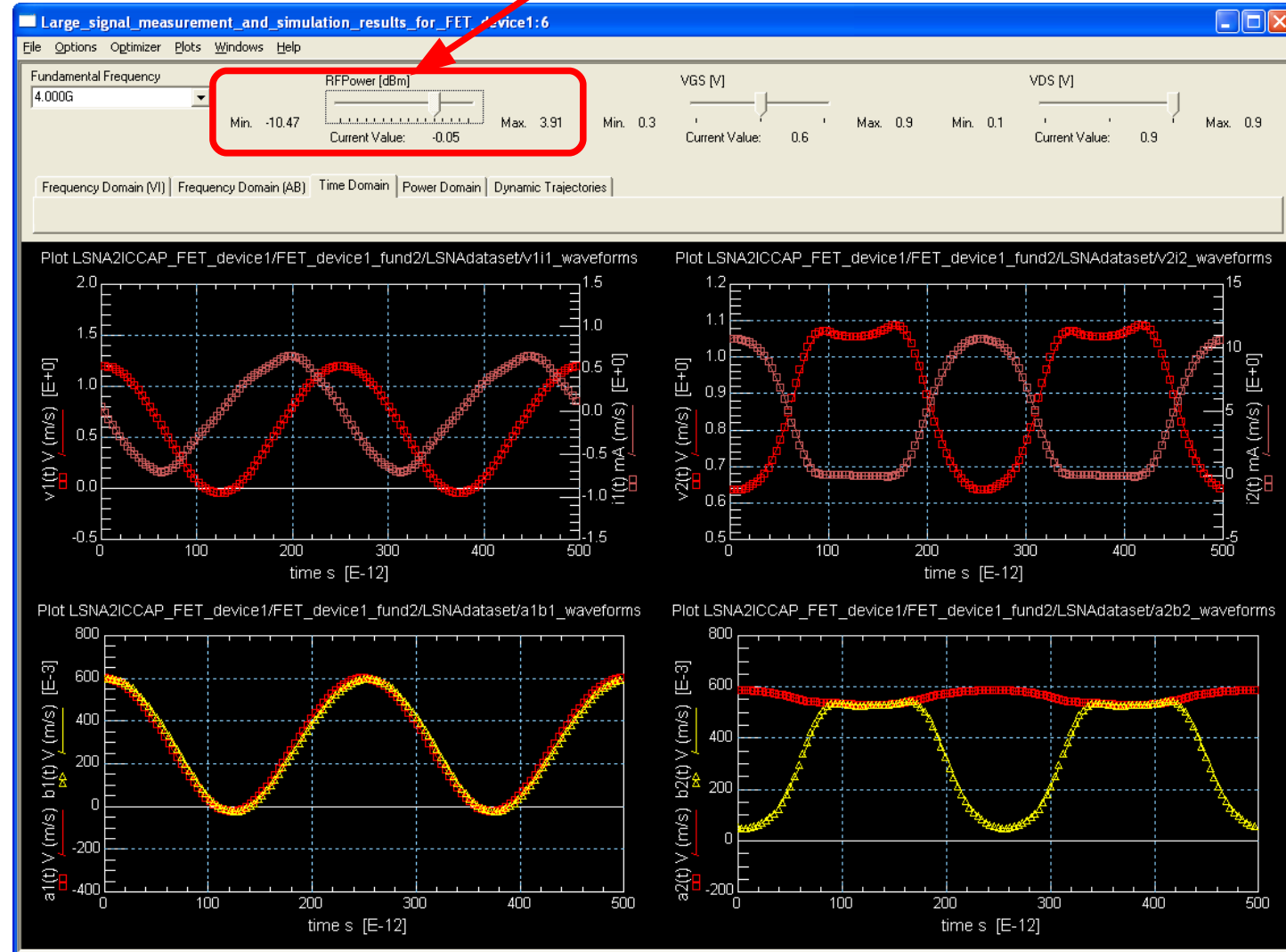
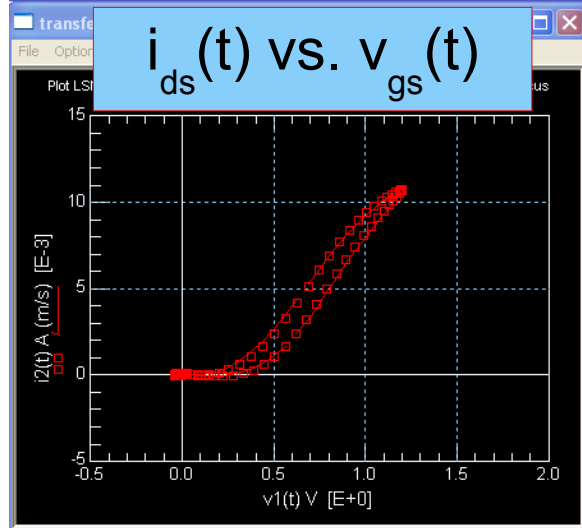
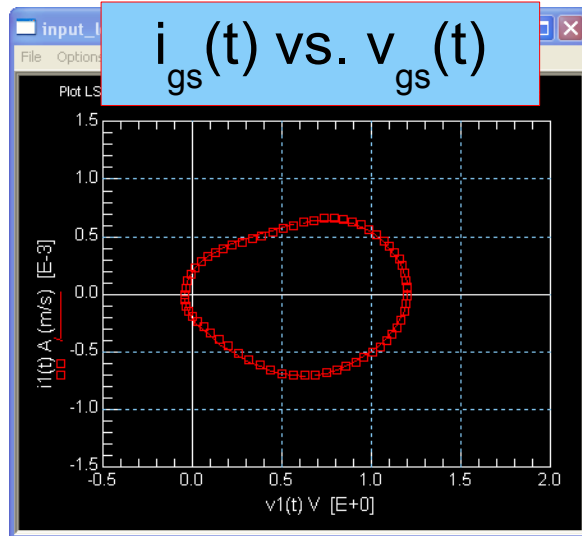
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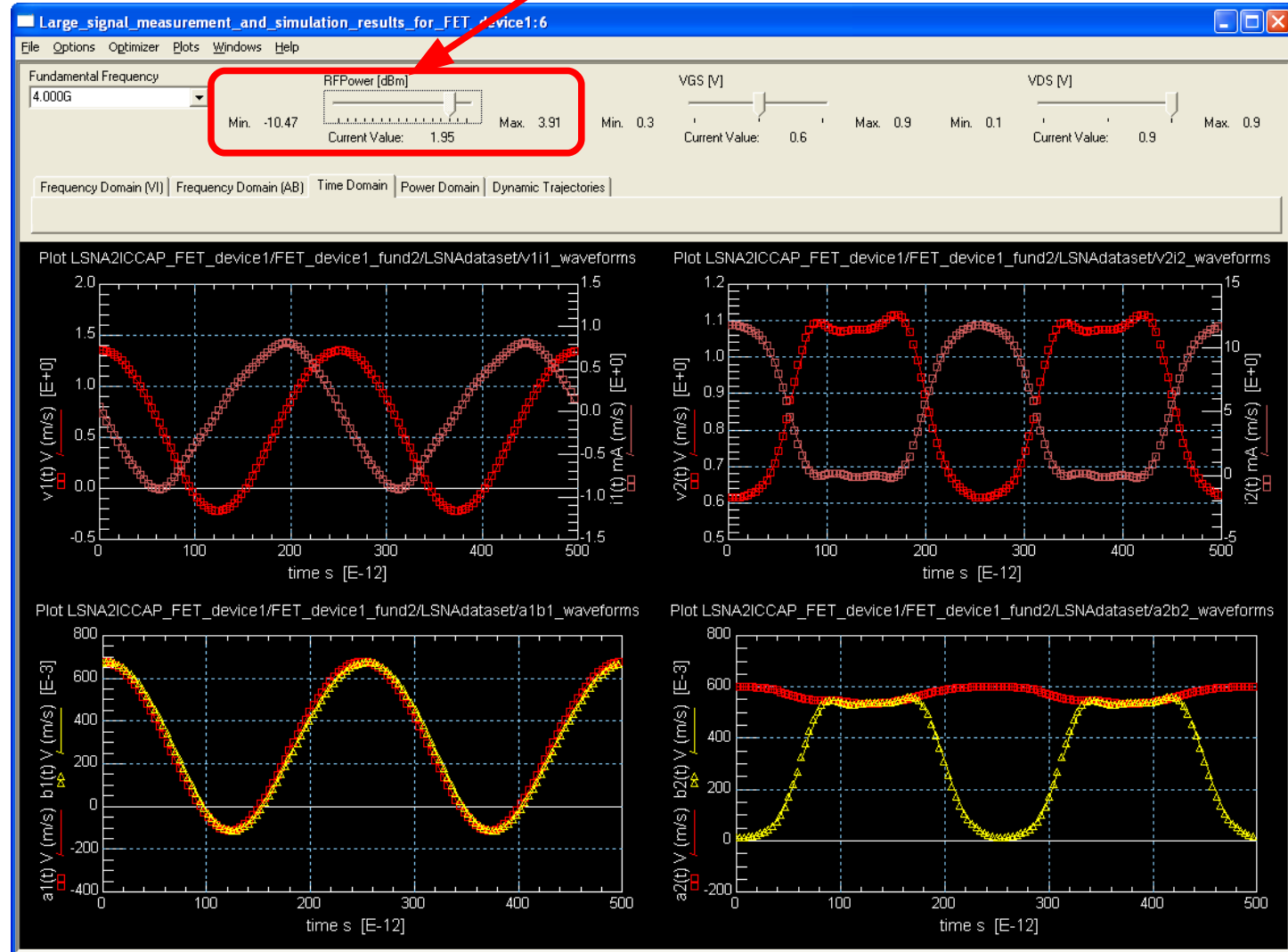
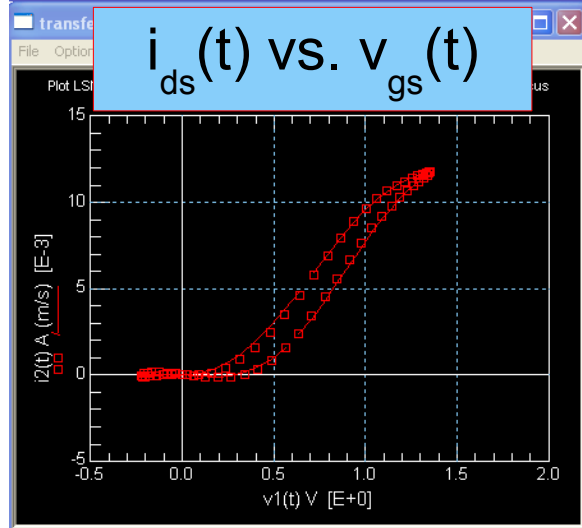
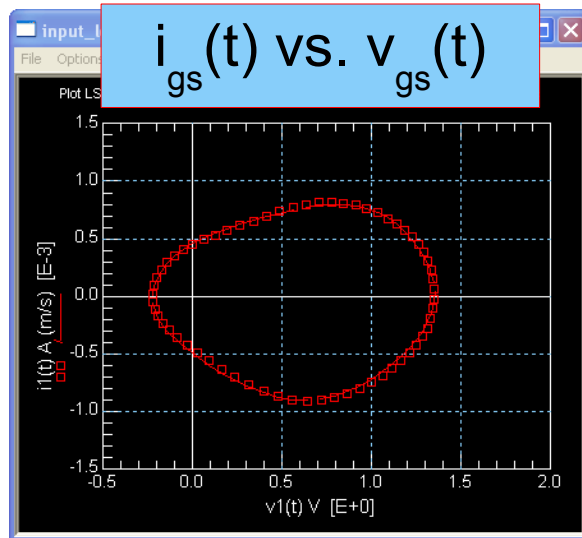
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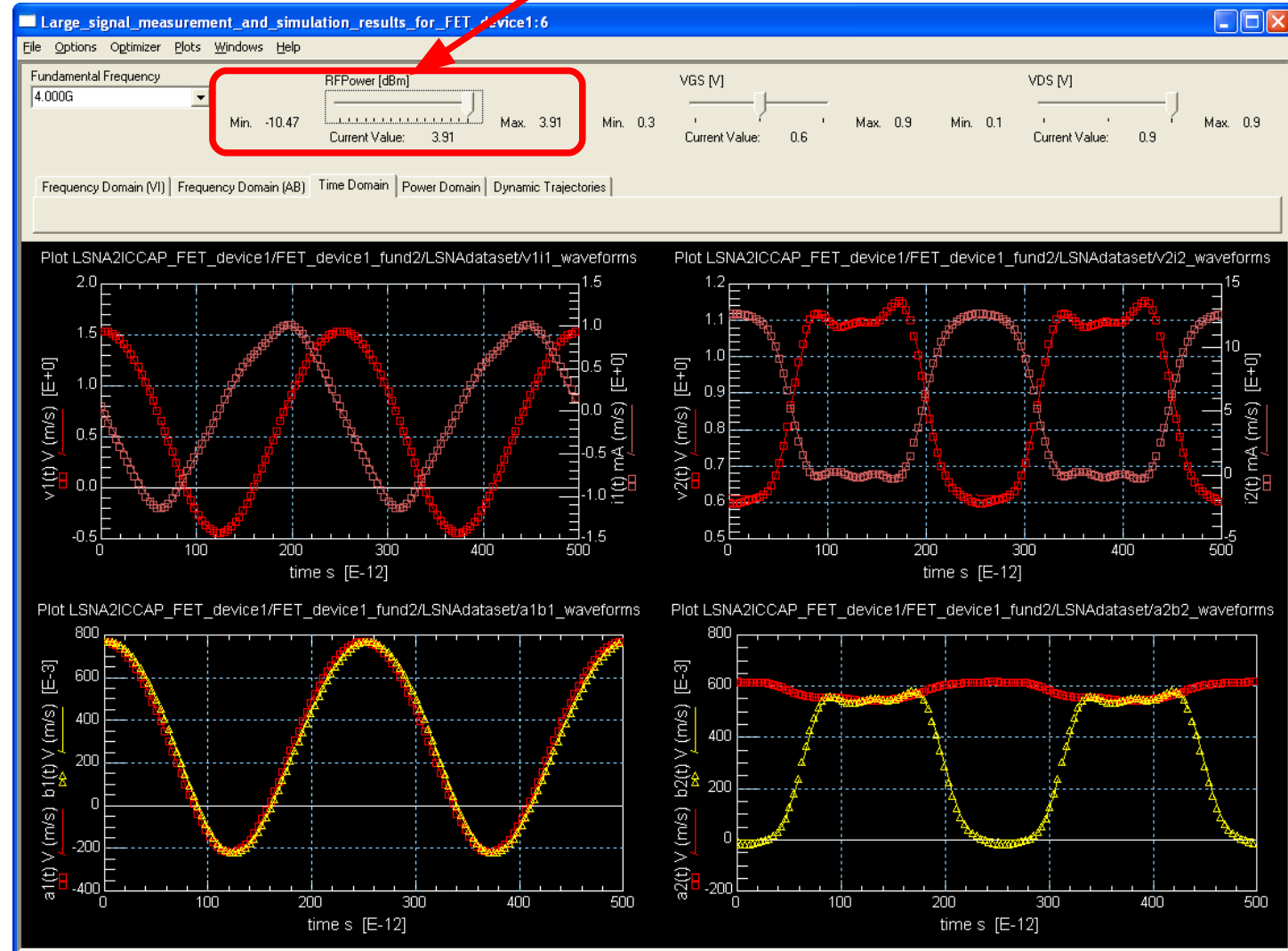
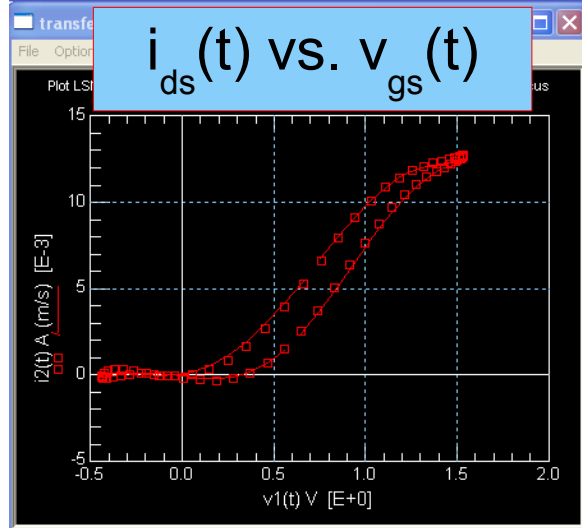
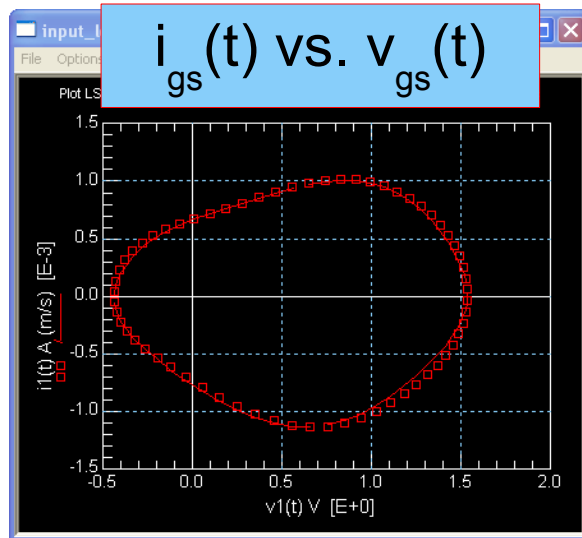
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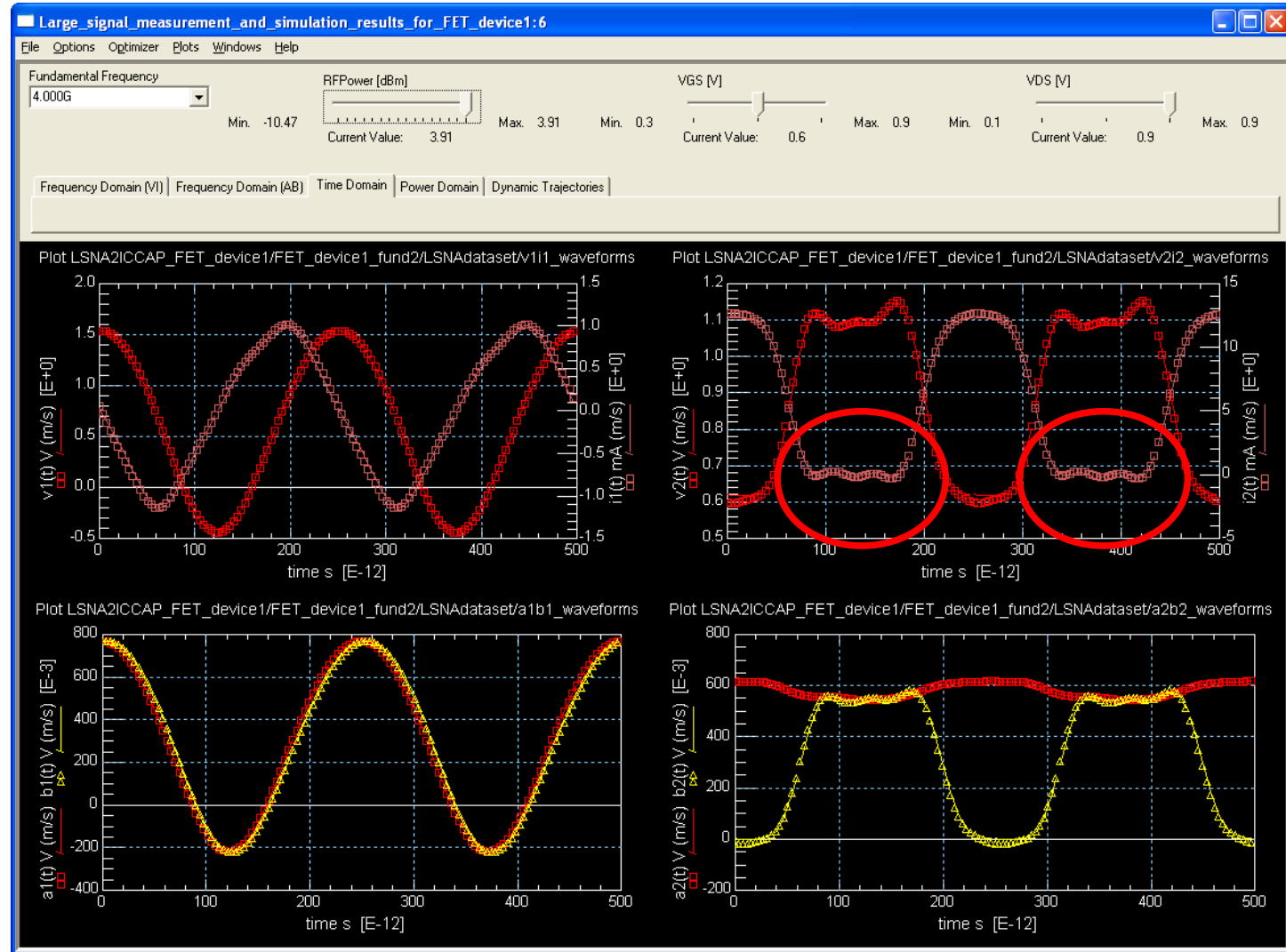
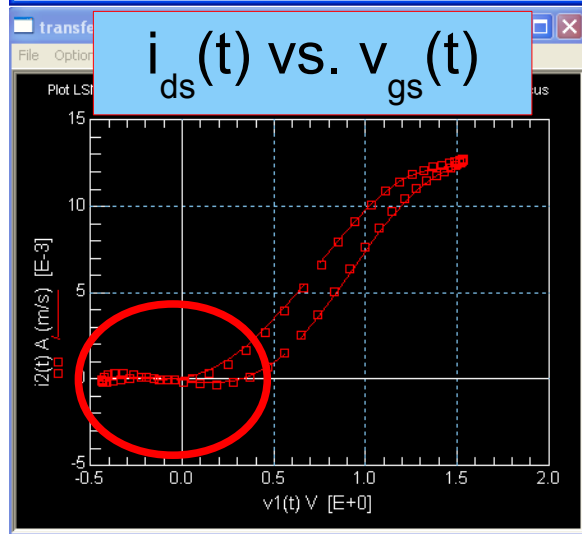
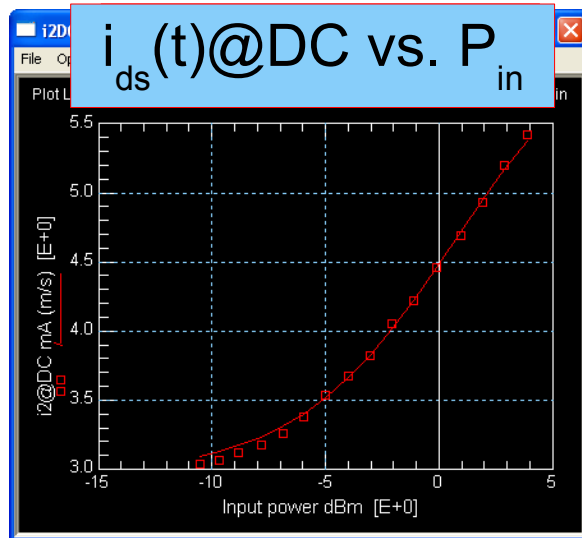
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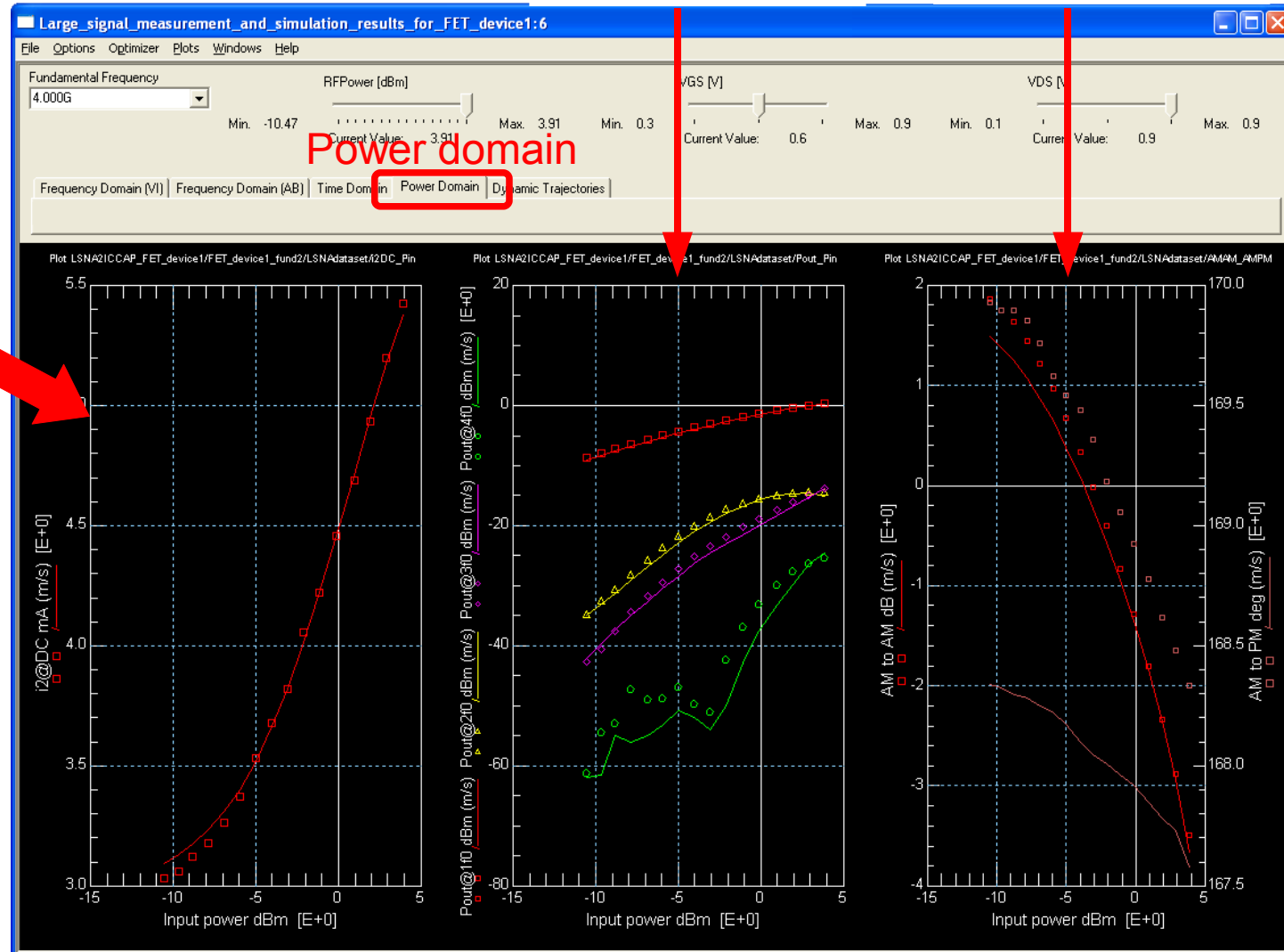
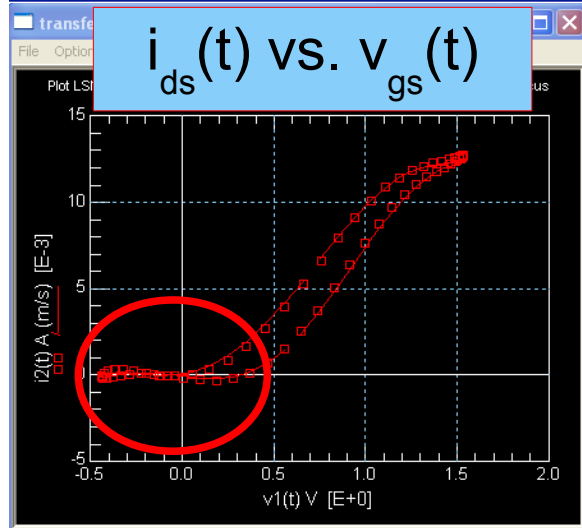
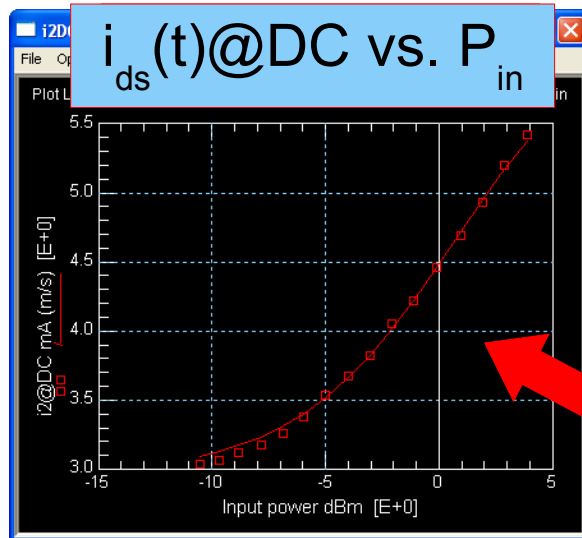
Self biasing effect

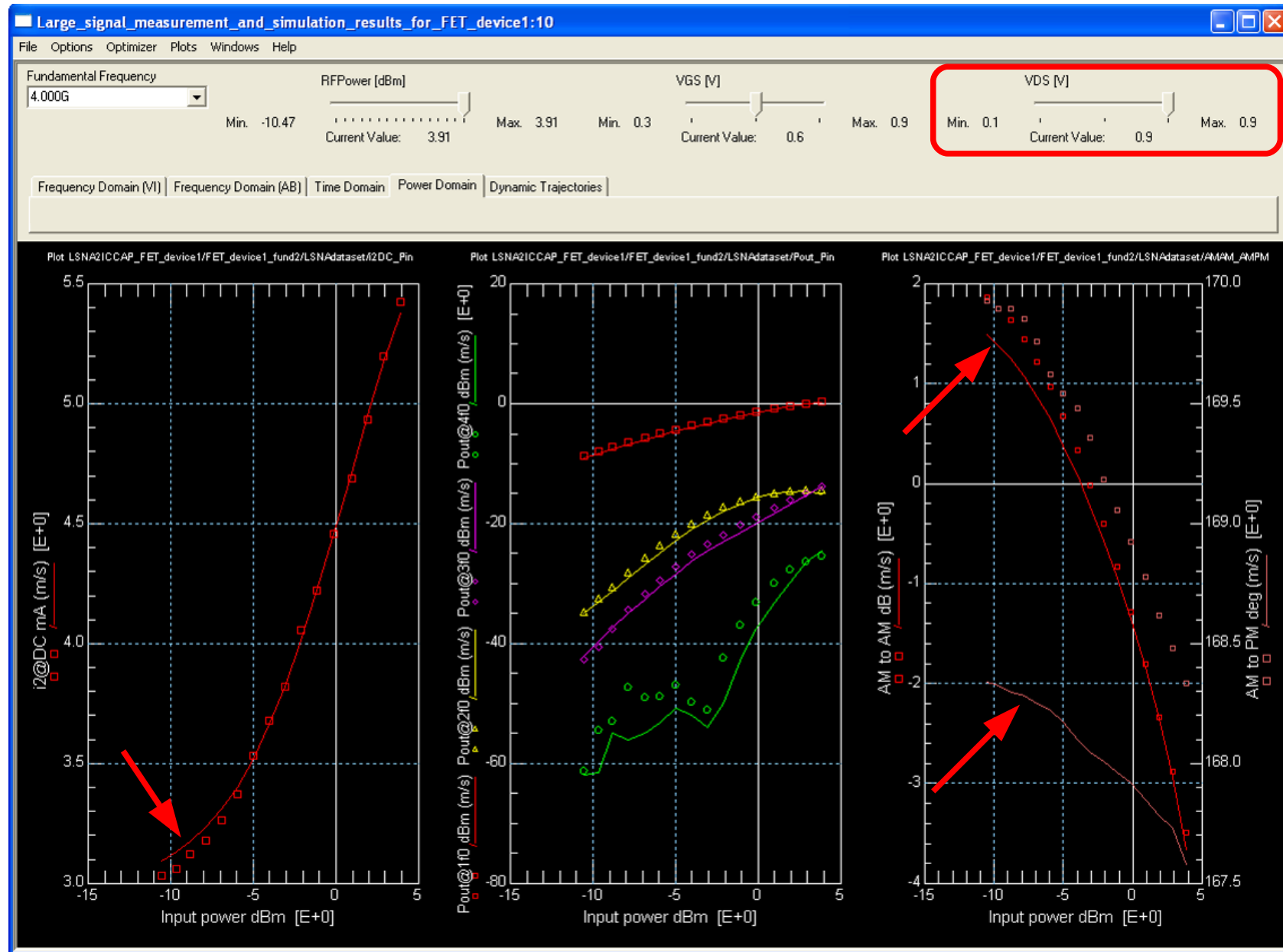


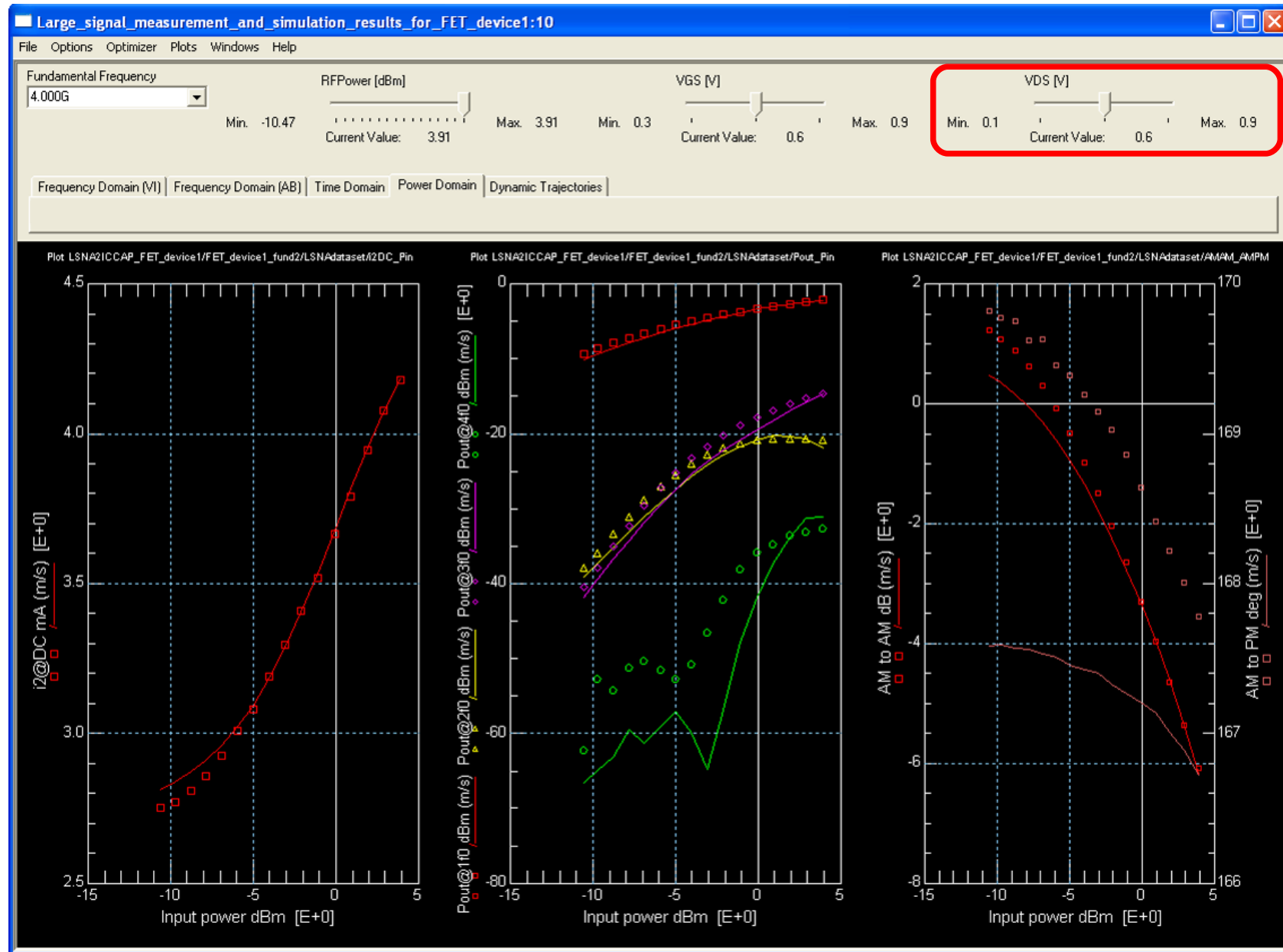
Self biasing effect

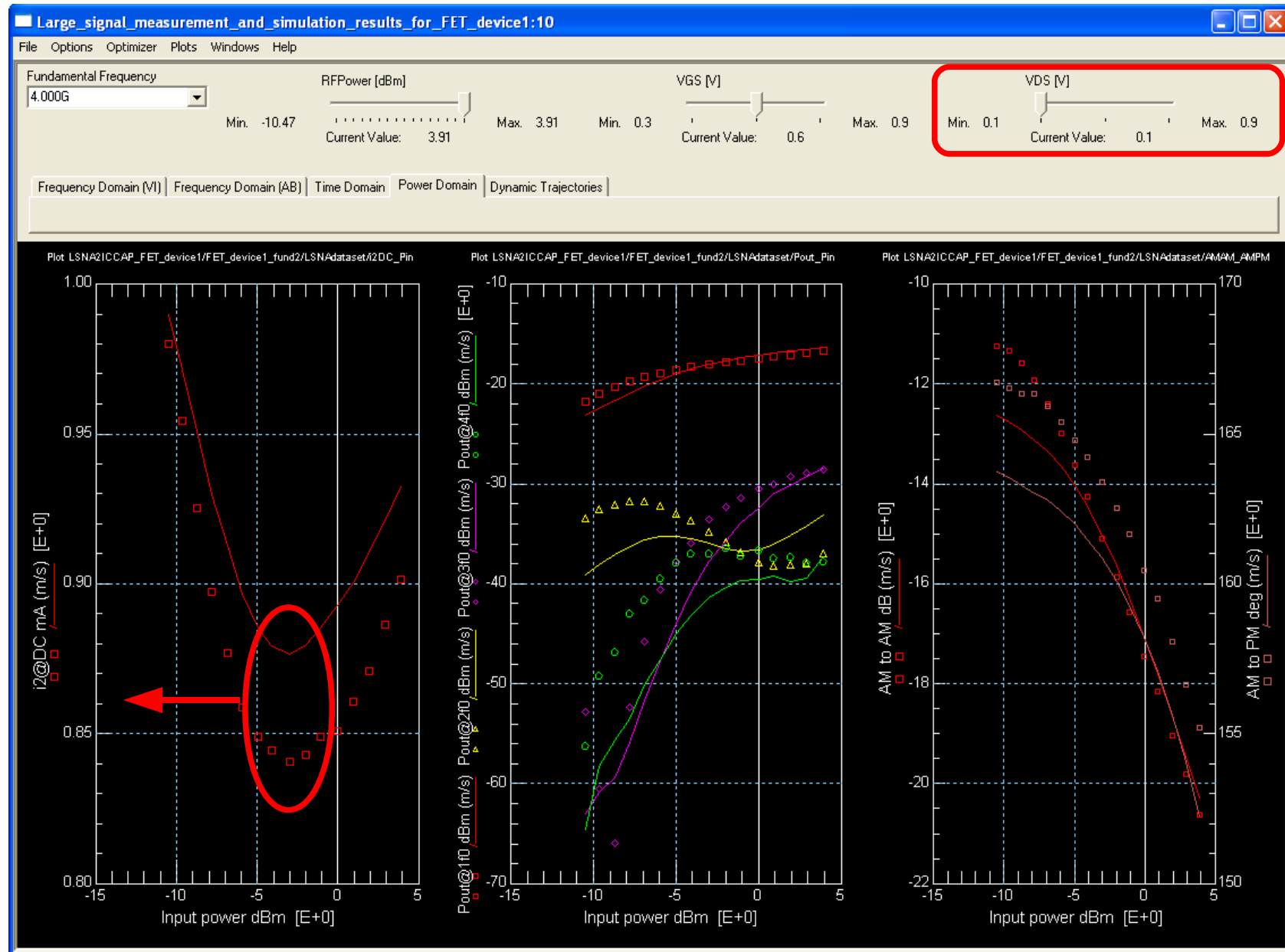
Harmonic
distortion

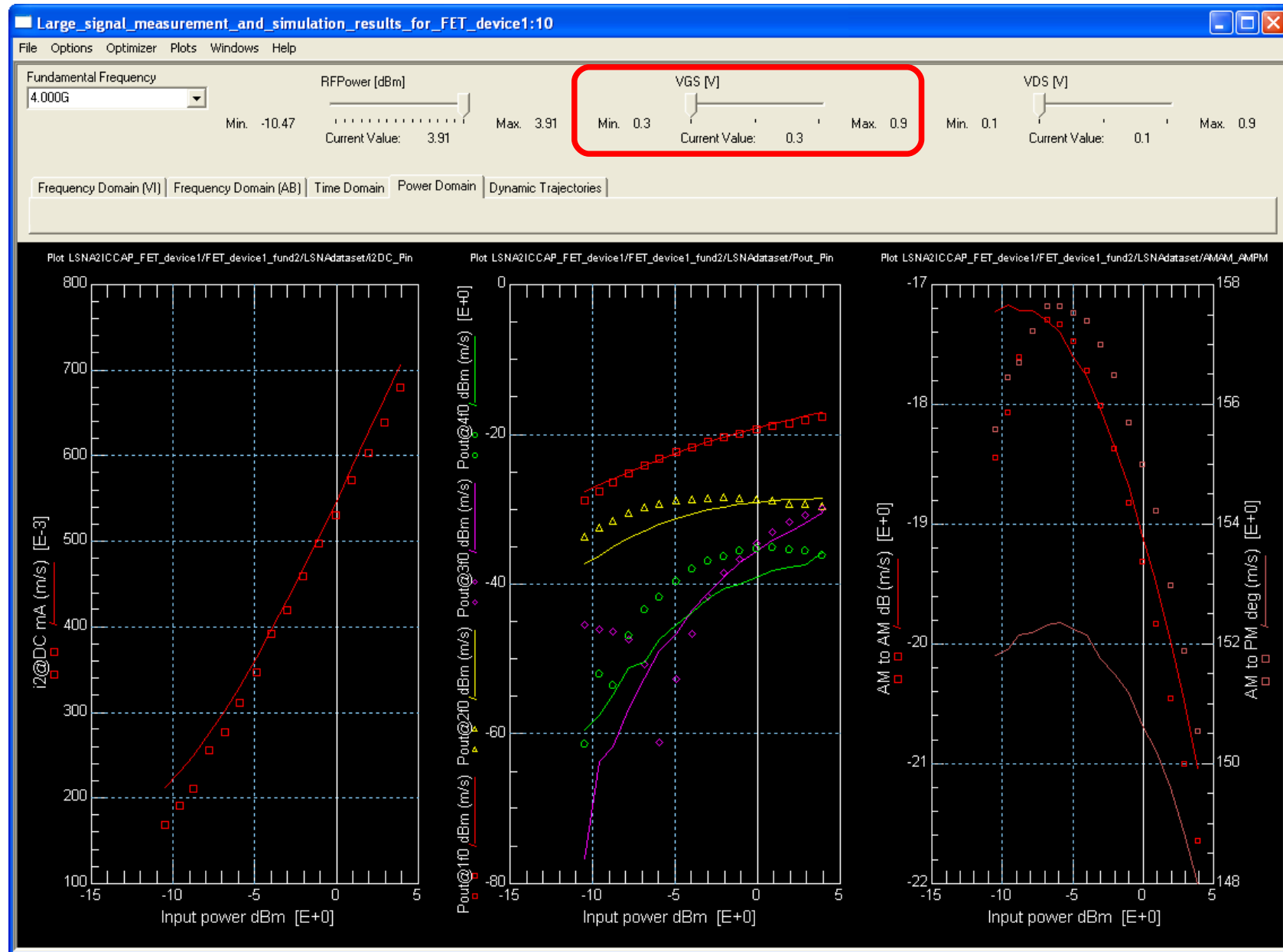
AM-AM
AM-PM

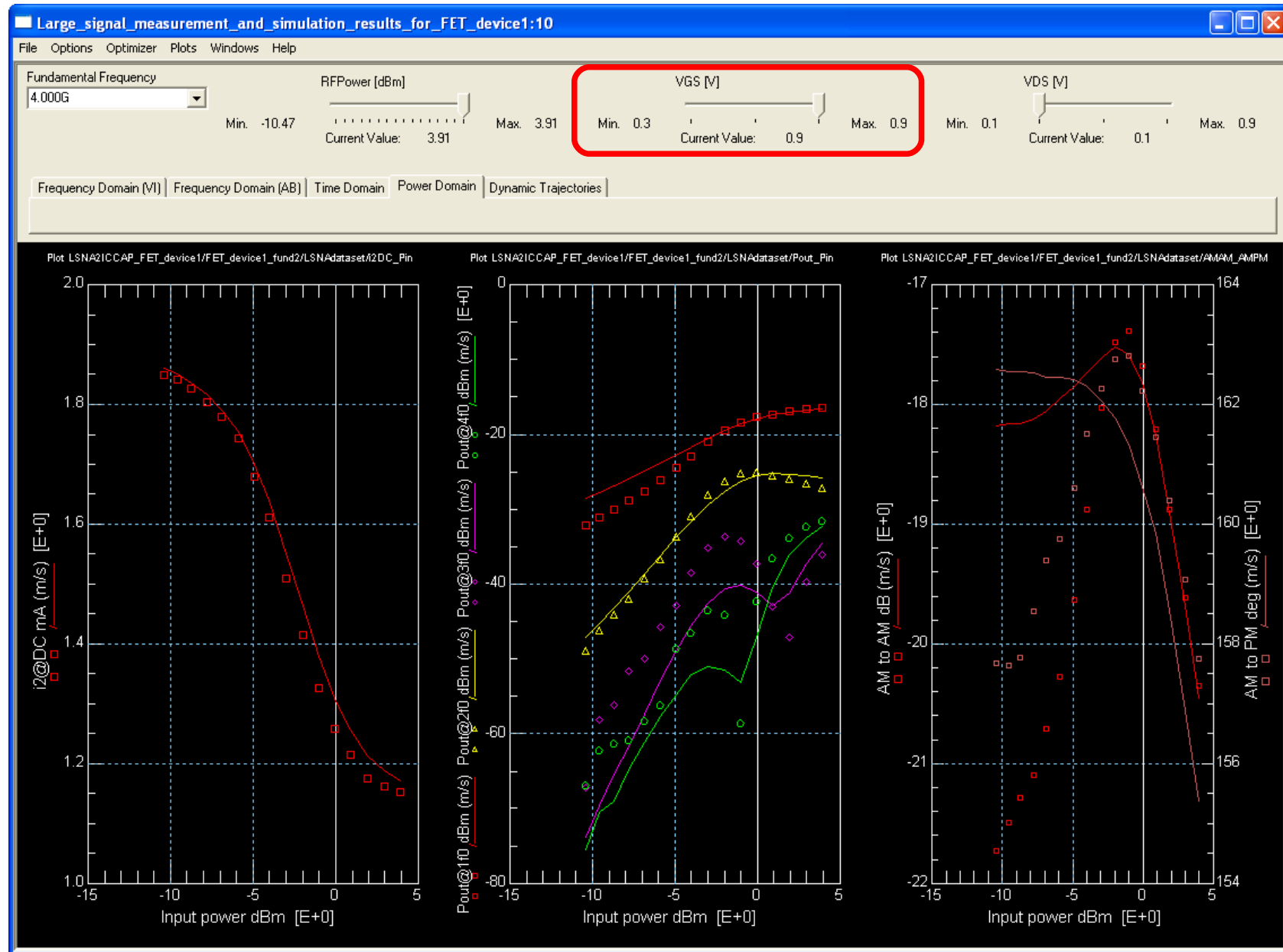


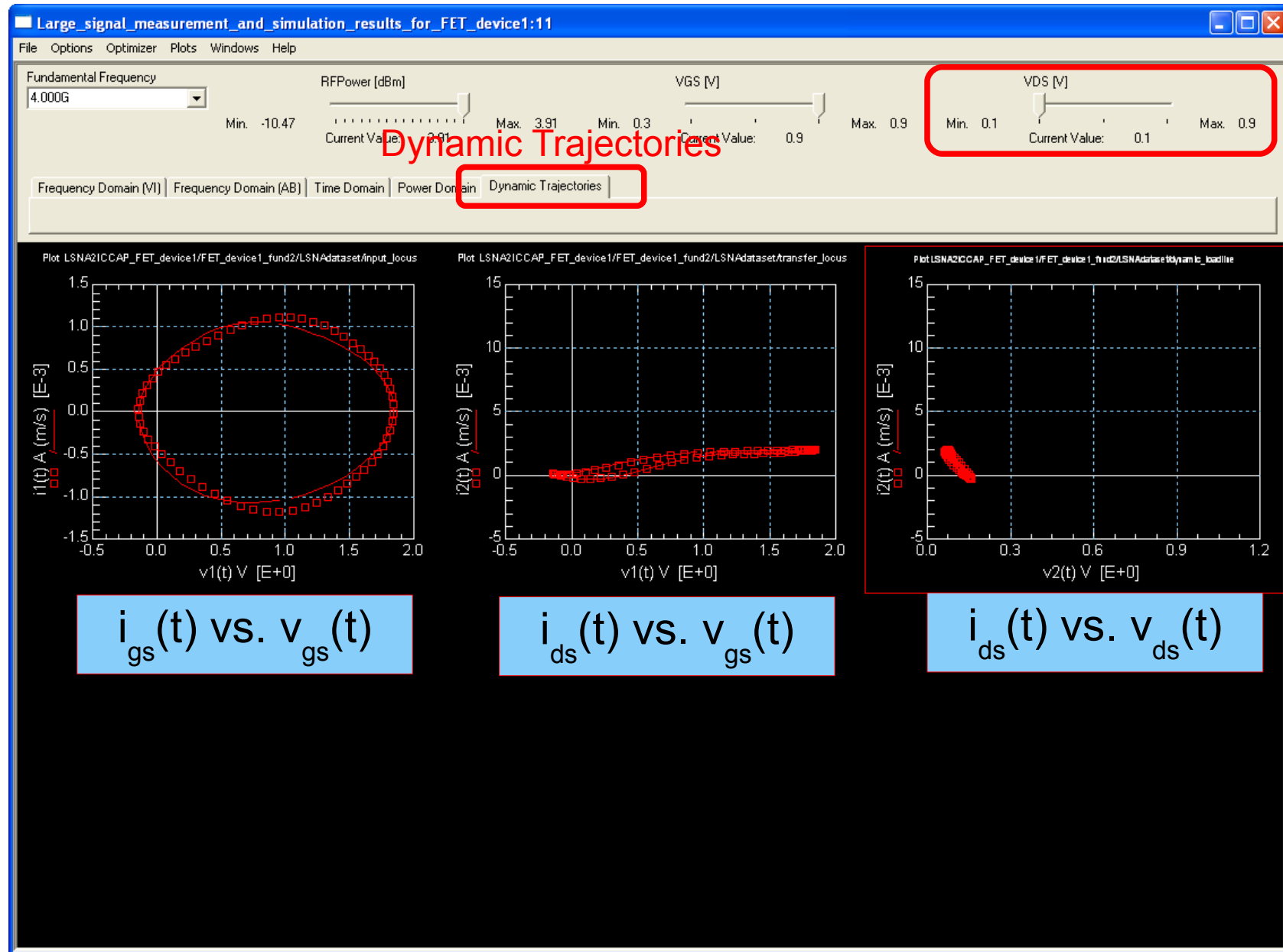


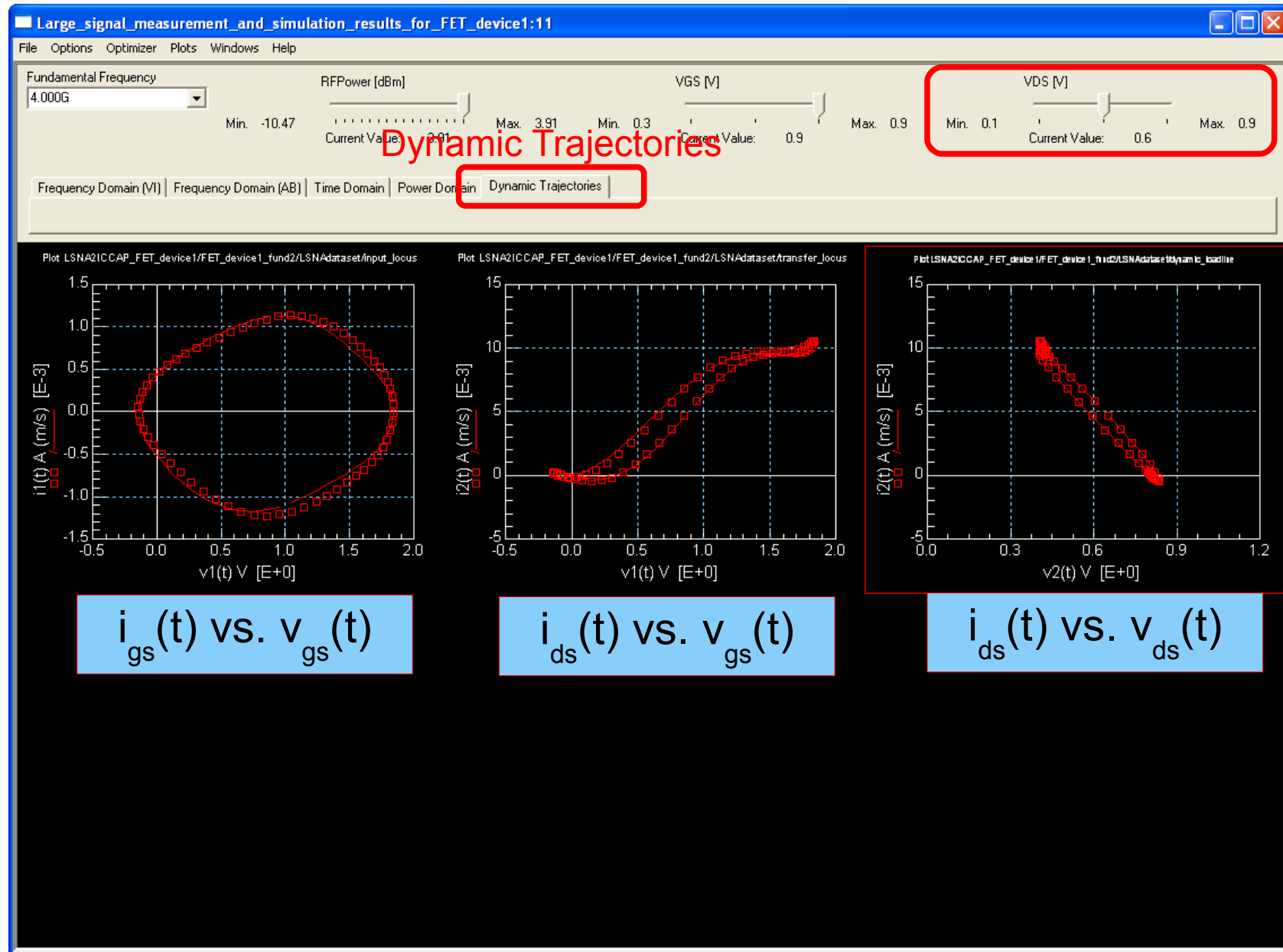


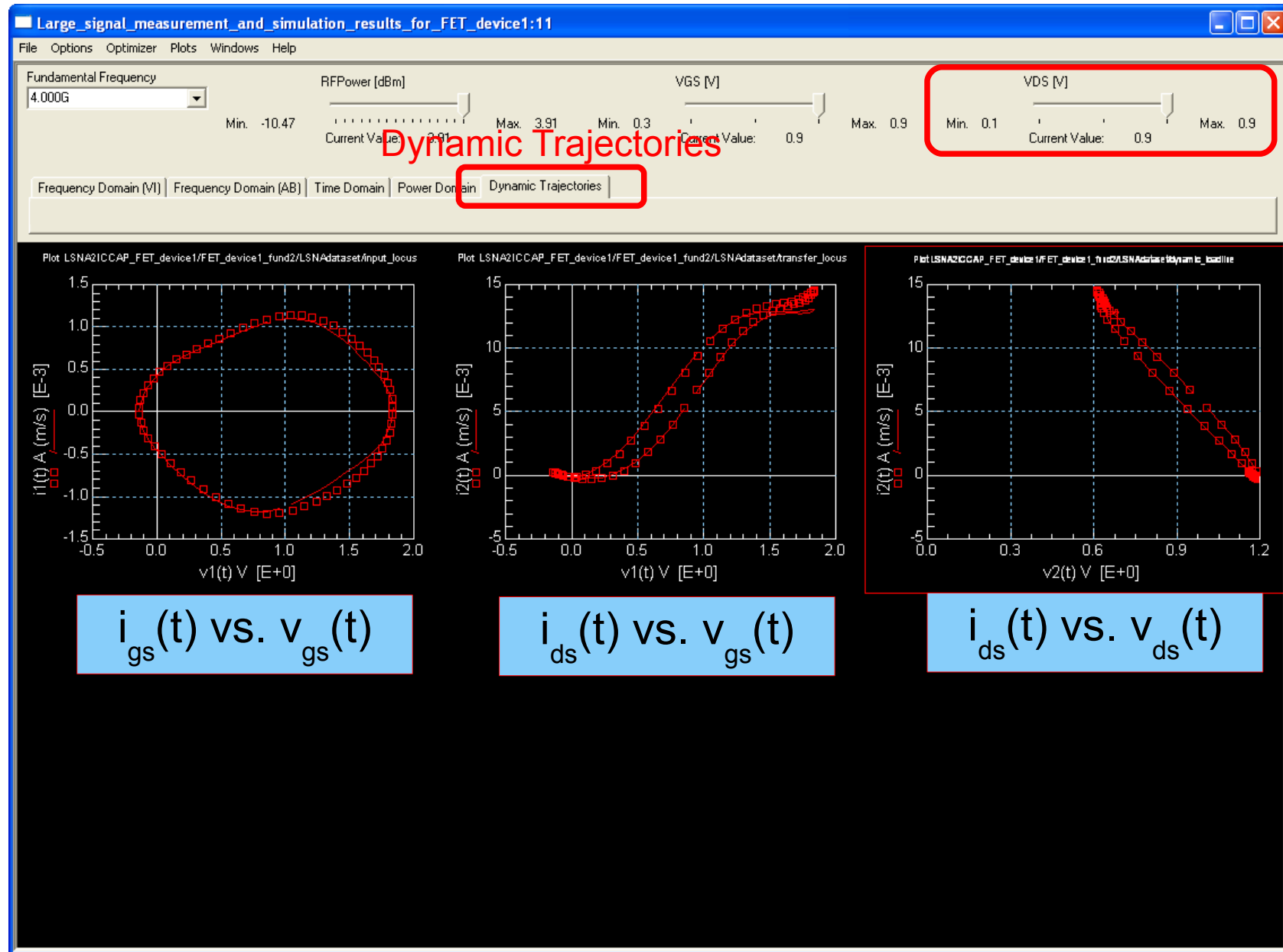


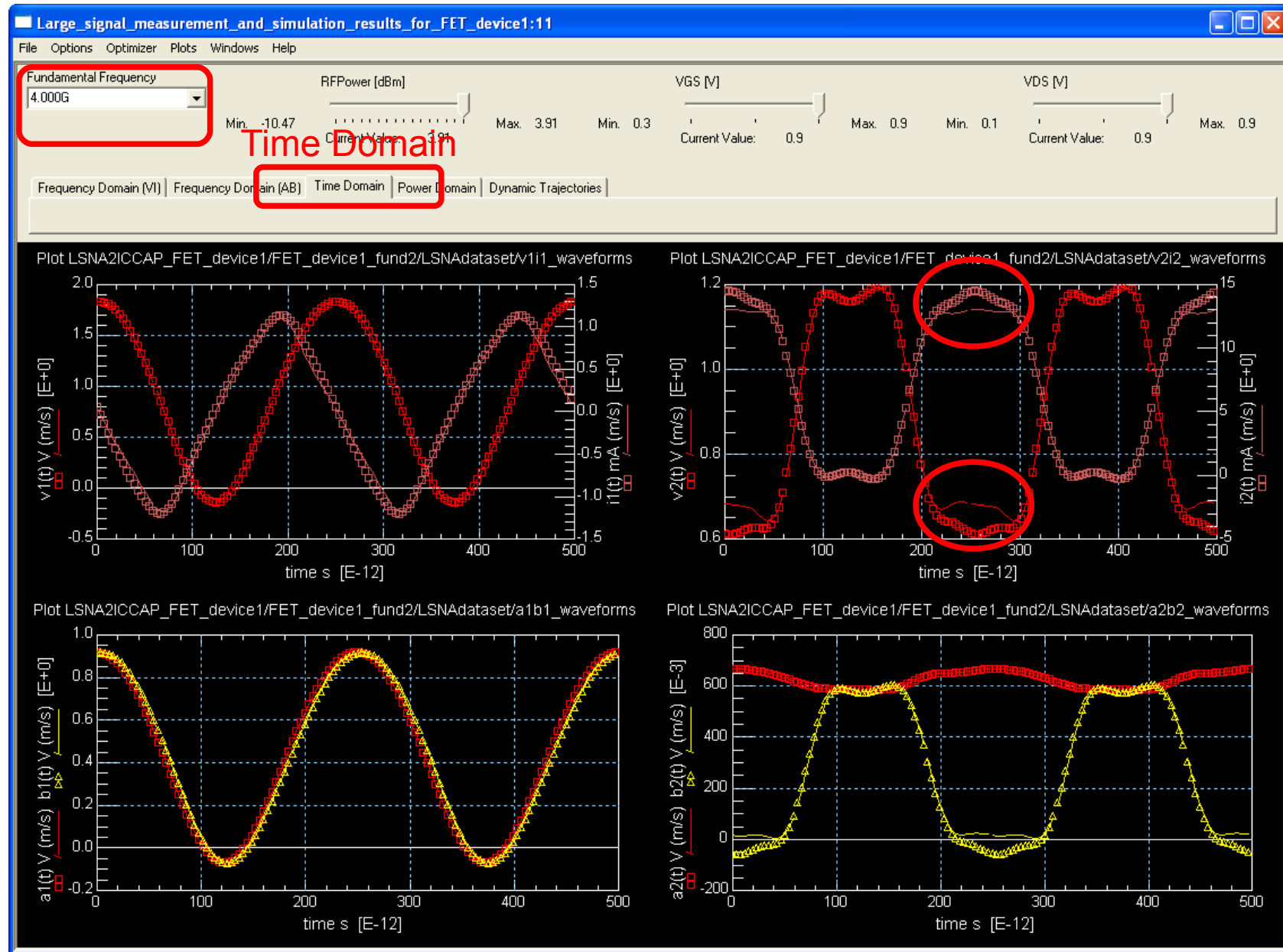


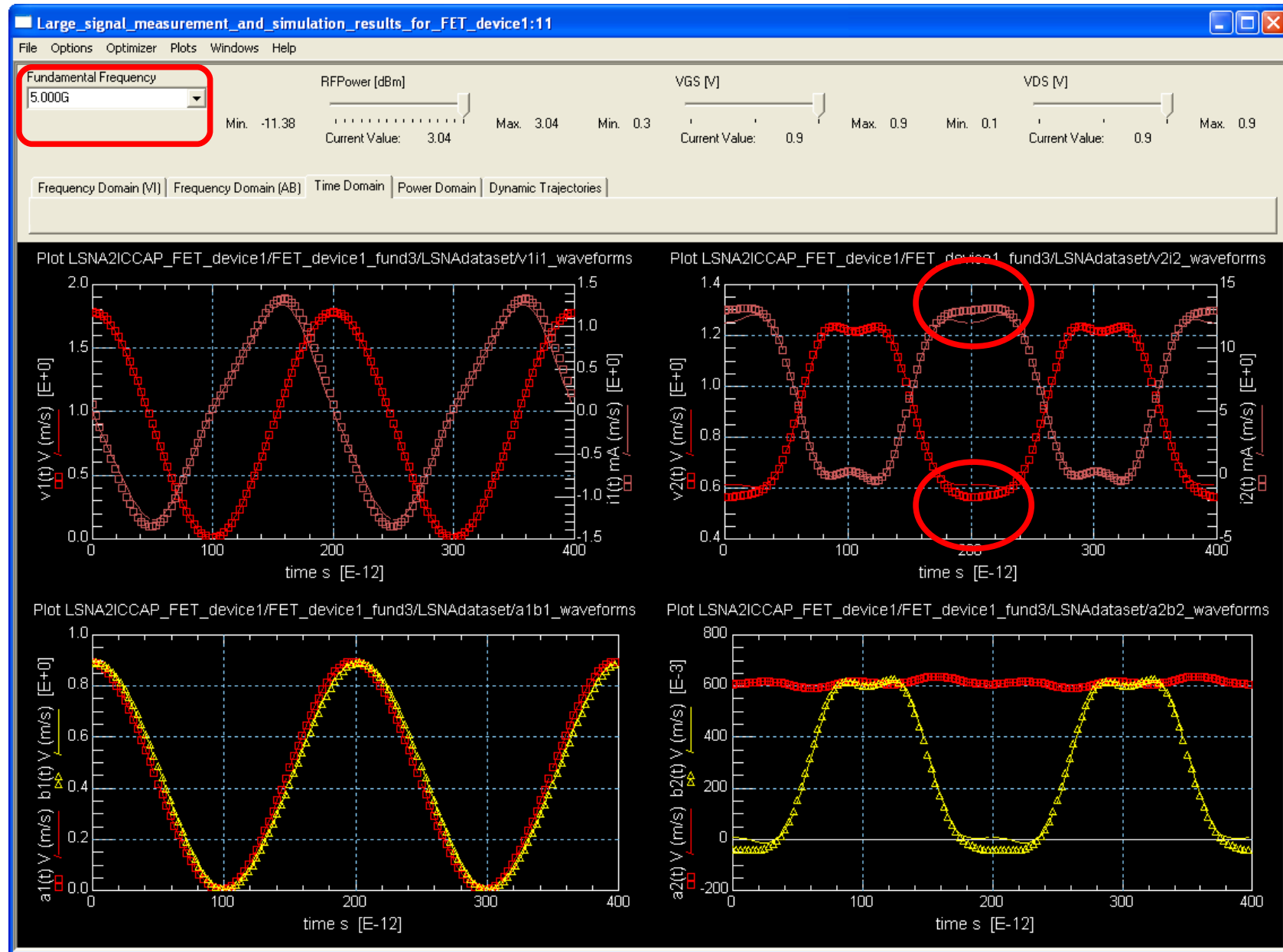


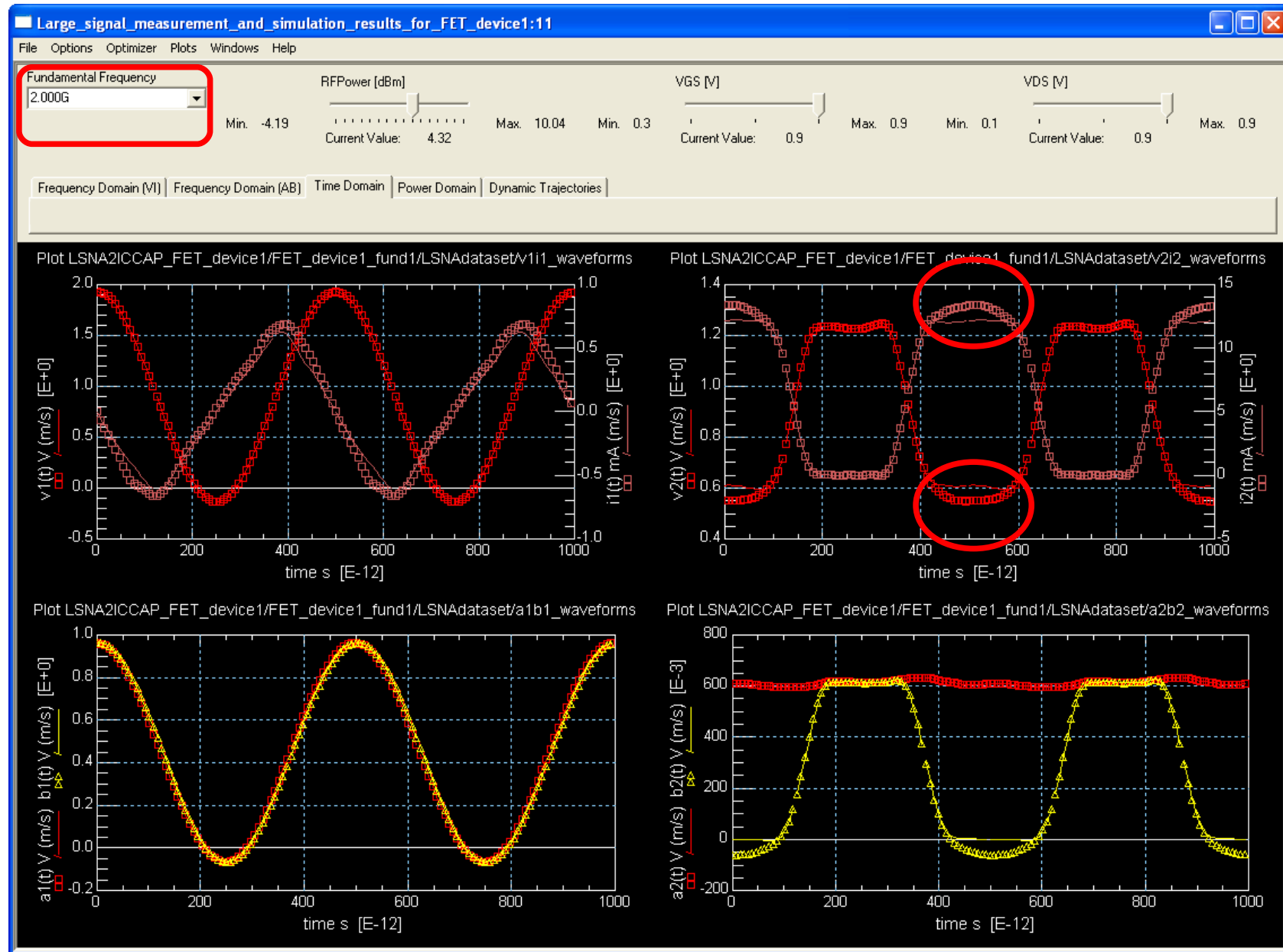


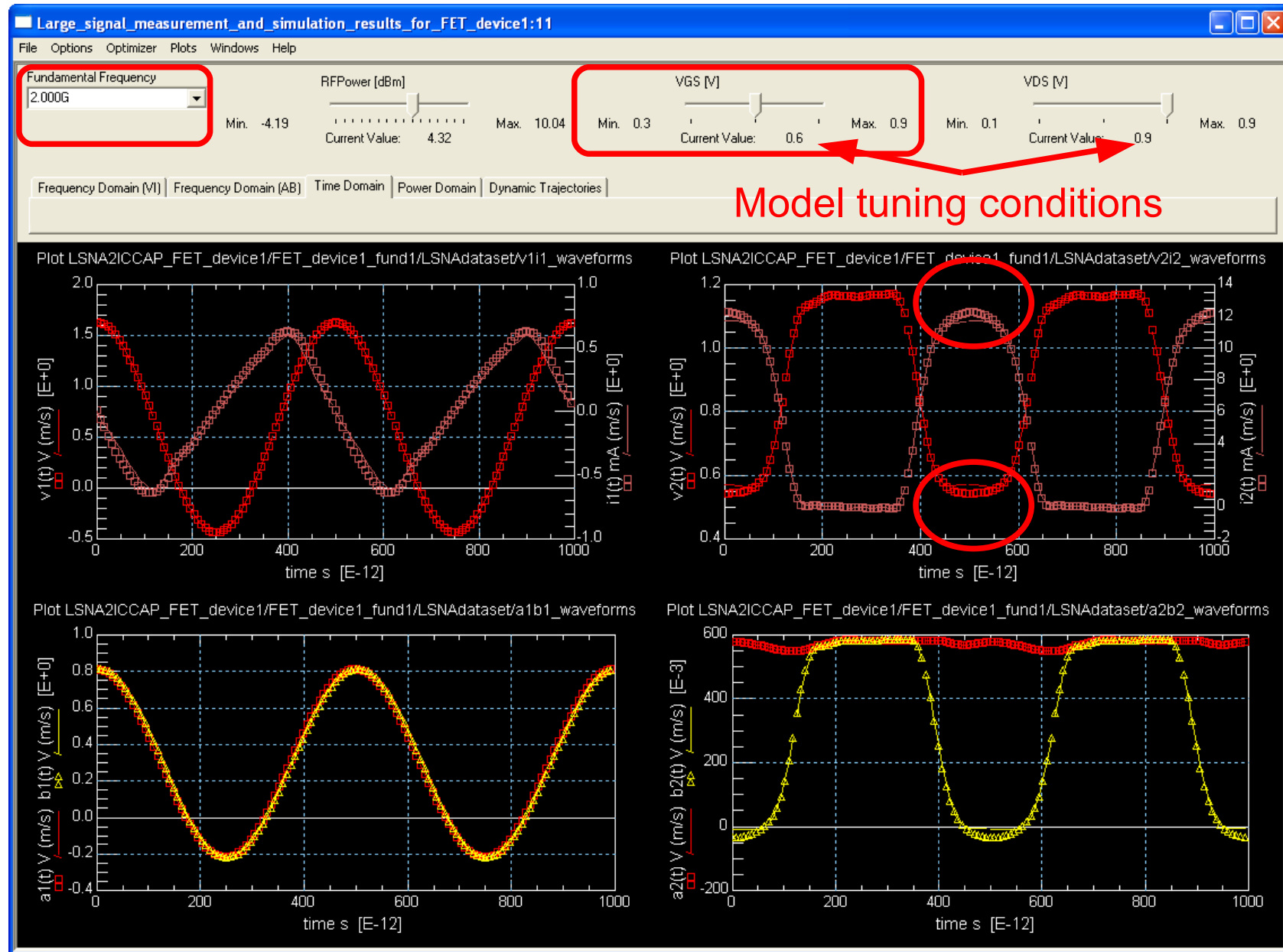












- Large-signal measurements + device modeling program =
 - **Complete** large-signal device characterization and model accuracy assessment under realistic signals,
 - **Simple access** and **improved usability** of the measured data,
 - Model **comparison** and **optimization**.